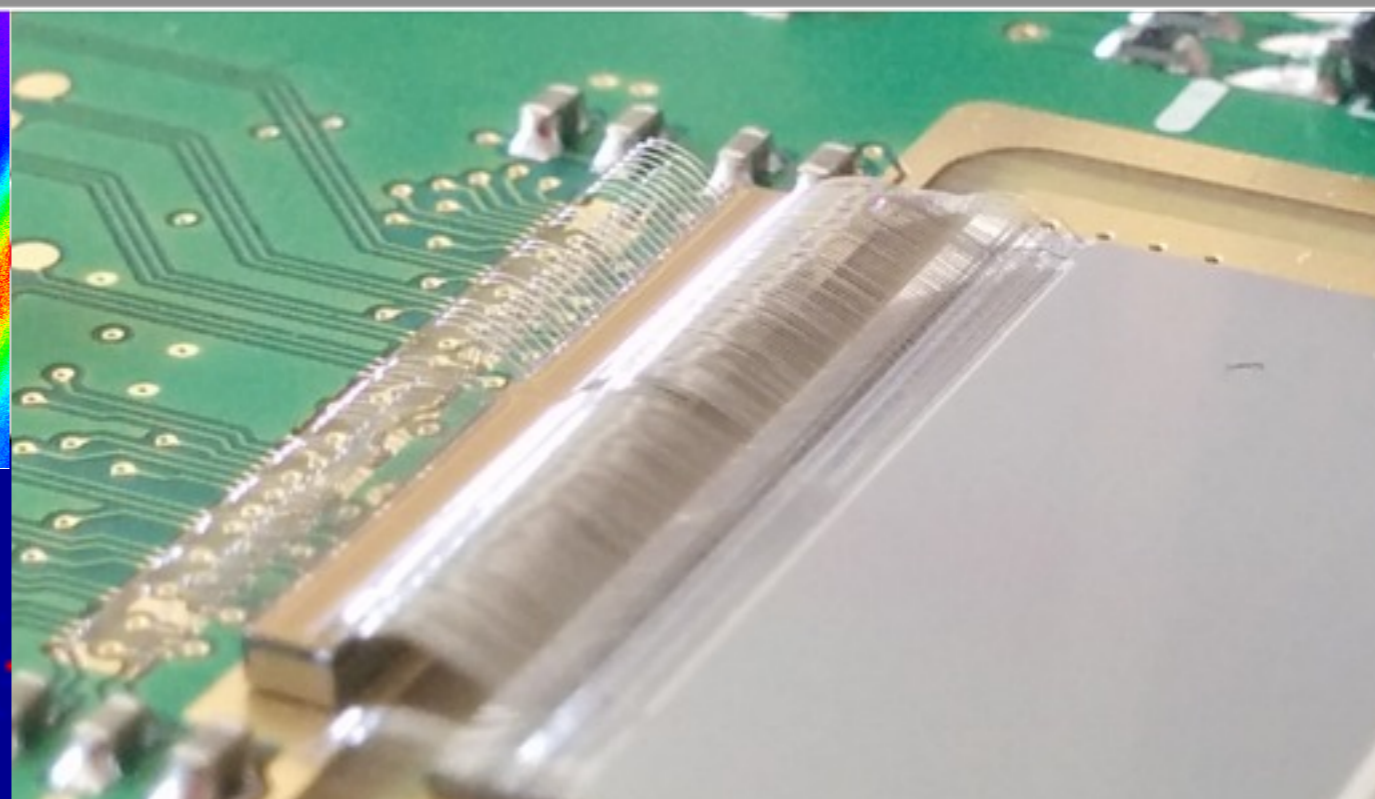
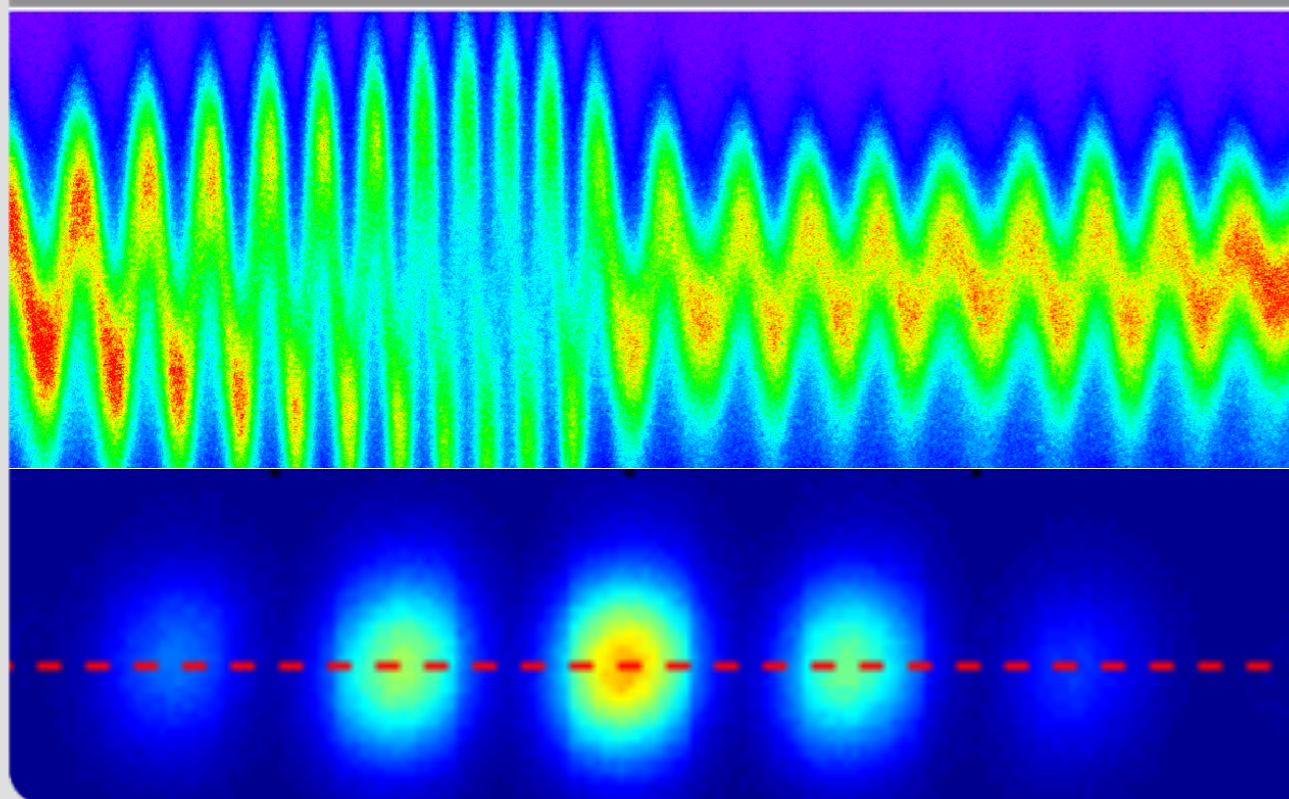


Short Bunches and Fast Diagnostics

Accelerator Science at the Karlsruhe Institute of Technology

Anke-Susanne Müller

ANKA Synchrotron Light Source at KIT



The Karlsruhe Institute of Technology



A legal unit



Merging of two missions



State University



National Research Center

Three tasks



Research



Higher Education



Innovation

What KIT stands for – Engineering Tradition



Karl Benz: inventor of the modern automobile

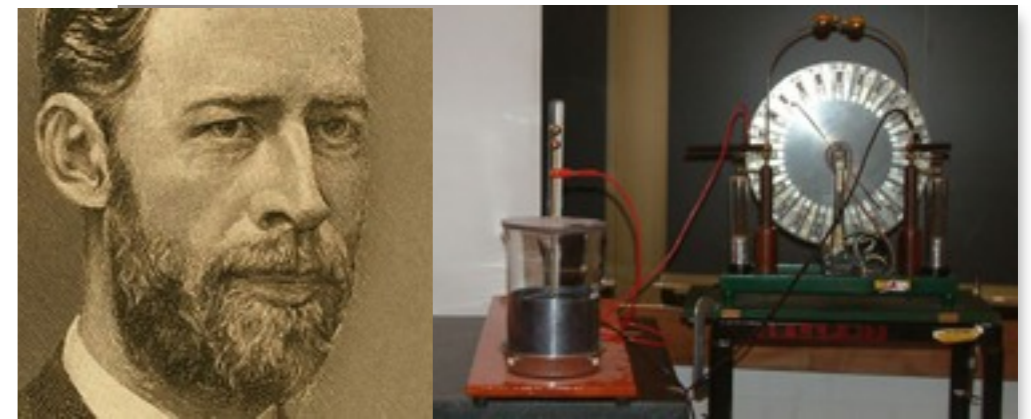


Ferdinand Braun:
inventor of cathode ray
tube → television



1984 first email in Germany

Heinrich Hertz: confirmation of
electromagnetic waves



Fritz Haber:
fixation of
atmospheric N_2
→ synthetic
ammonia

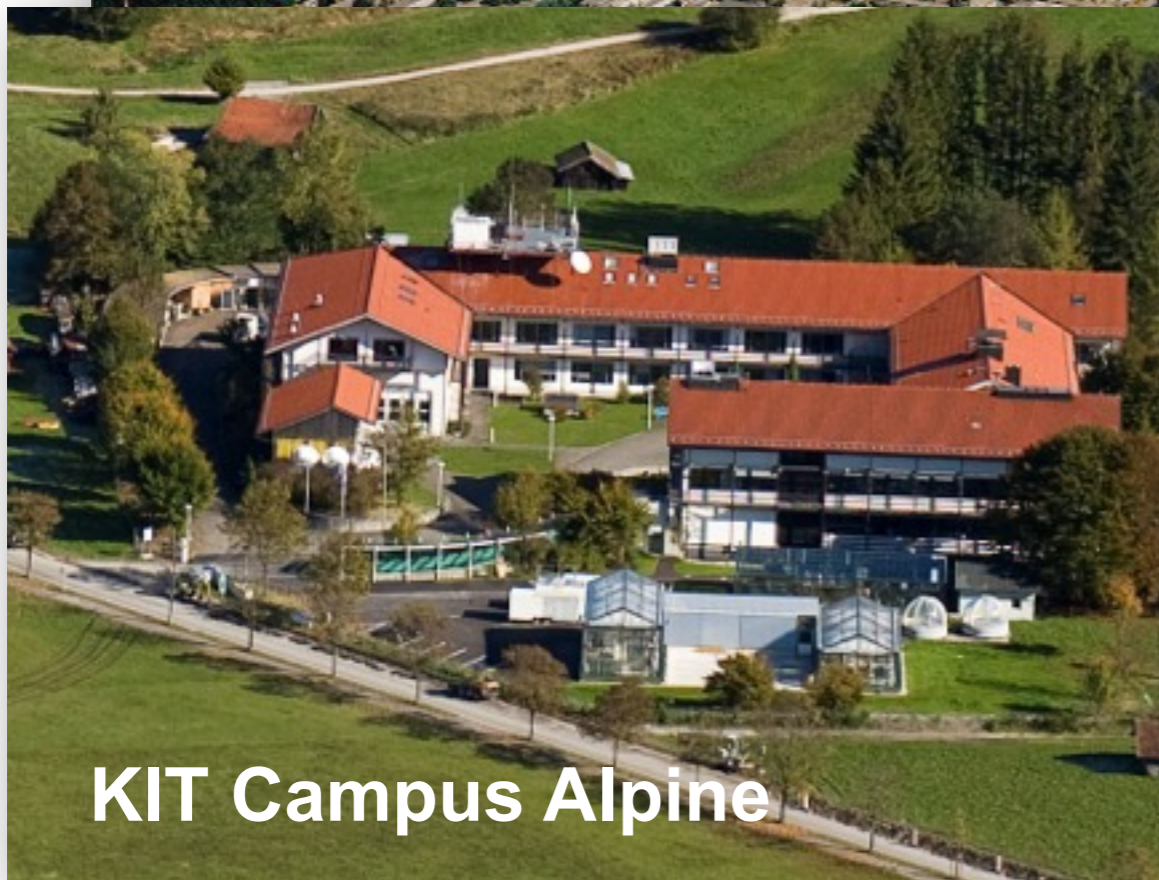
KIT – Helmholtz Center and State University



KIT Campus North



KIT Campus South



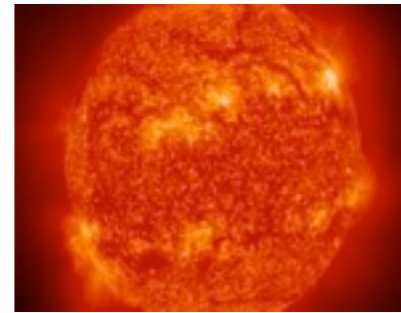
KIT Campus Alpine



Helmholtz Institute Ulm

The KIT-Centers combine cross-sectoral research and innovation topics

- Currently seven KIT-Centers
- Platforms for cross-sectoral research and innovation activities
- Pooling of teaching activities, for example, in graduate schools
- Showcase for the key topics for research at KIT
- Interdisciplinary working-environment
- Creating synergies
- Communication platforms



Energy



Climate and Environment



Mobility Systems



Humans and Technology



Elementary Particle and Astroparticle Physics



Information Systems Technologies



Materials Structures Functions

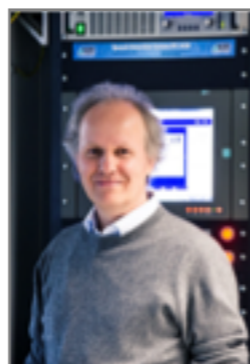
Accelerator & detector development at KIT



Andreas Kopmann
Fast DAQ systems



Ivan Peric
ASICs and
detectors



Marc Weber
Detectors



John Jelonnek
Pulsed power and
microwave technology



Erik Bründermann
THz Technology



Jürgen Becker
Detectors



Christian Koos
Silicon photonics,
Tb/s communications



Sara Casalbuoni
Superconducting IDs
Diagnostics



Anke-S. Müller
Accelerators



Axel Bernhard
Superconducting IDs



Michael Siegel
Superconducting
terahertz sensors



Mathias Noe
Superconducting
Technology

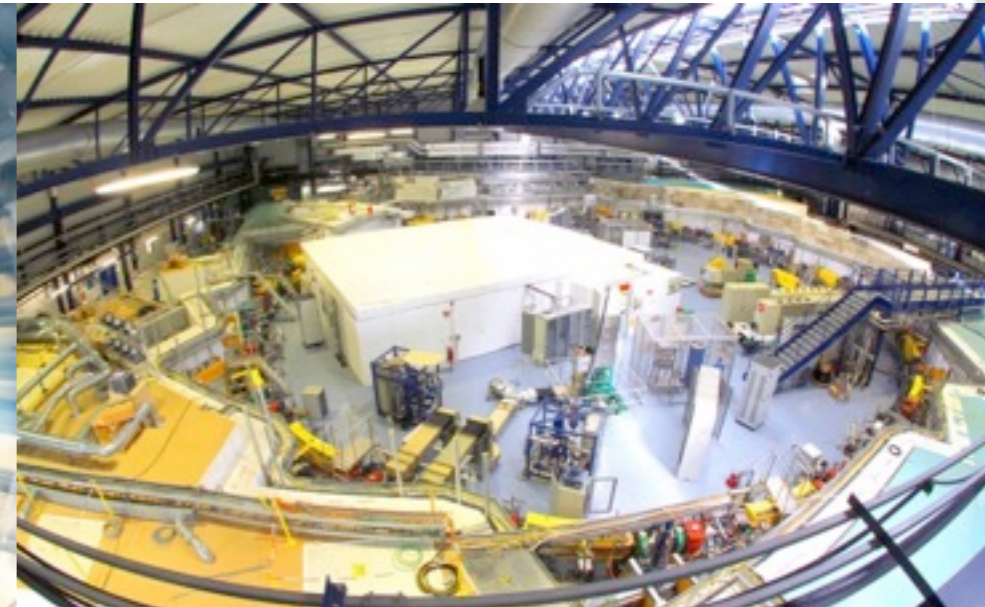
Some facilities and labs at KIT



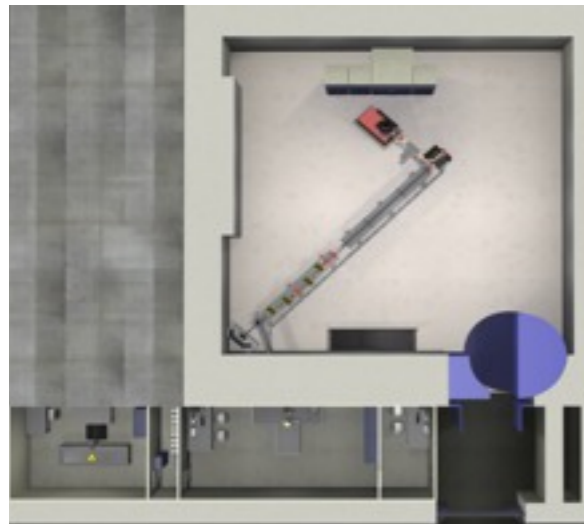
Hybrid assembly lab (IPE)



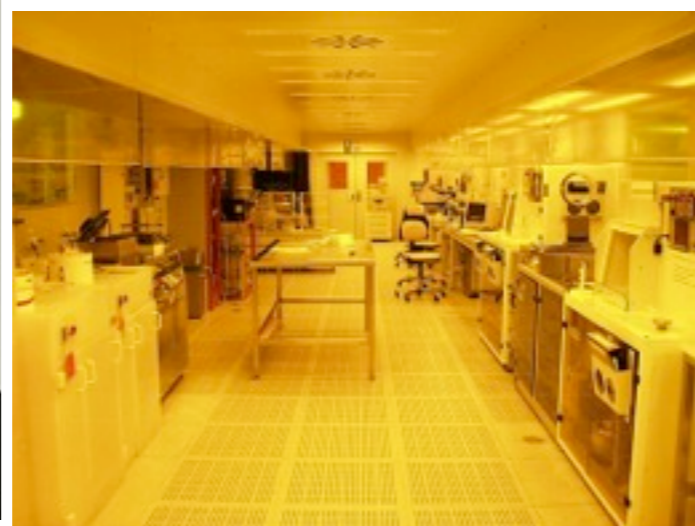
KATRIN Neutrino experiment



ANKA 2.5 GeV Light Source



FLUTE fs linac



Karlsruhe Nano Micro Facility



*Production of thin NbN-films
with reactive magnetron
sputter (IMS)*

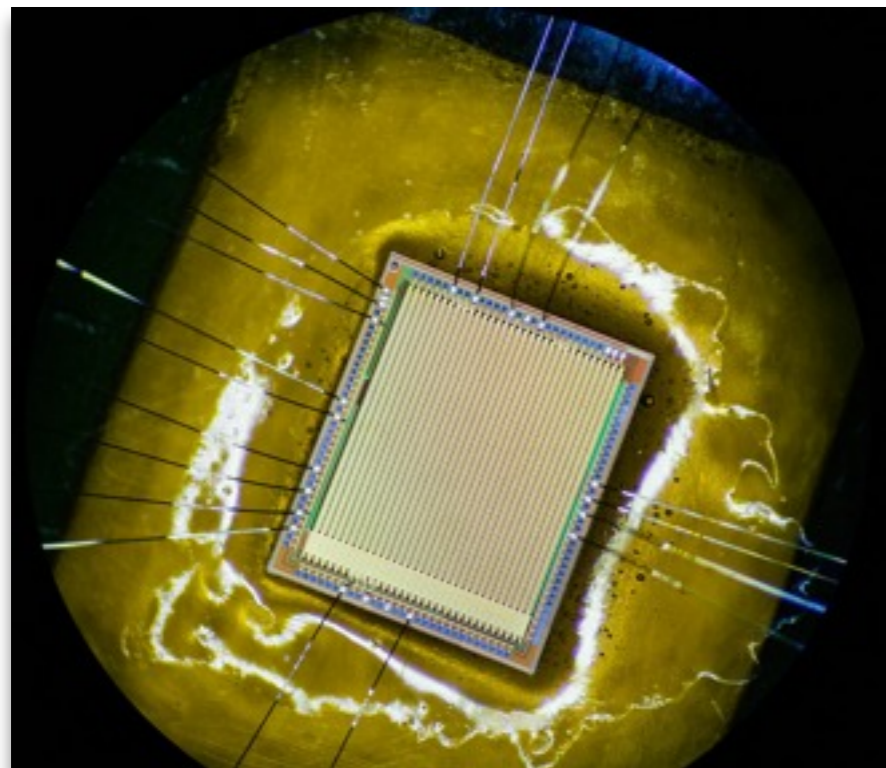
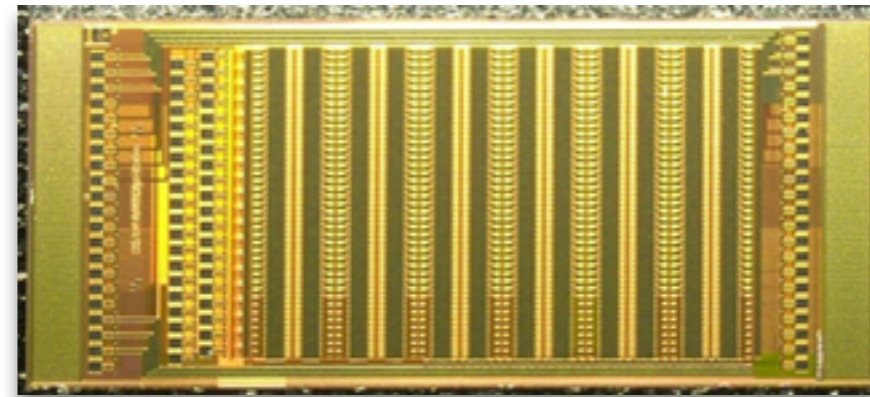


Irradiation facility (IEKP)

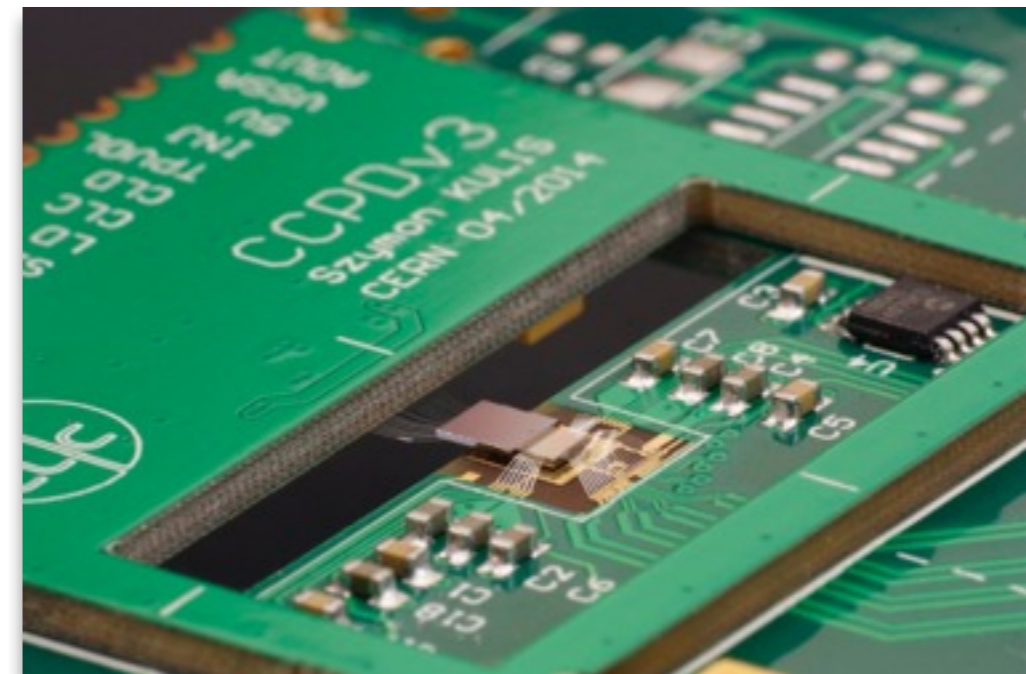
HV-CMOS Sensors



- Fast
- Radiation - hard
- Integrated read-out electronics
- Collaborations with University of Geneva, University of Liverpool, University of California Santa Cruz, Universität Heidelberg, Institut de fisica d'altas energies Barcelona



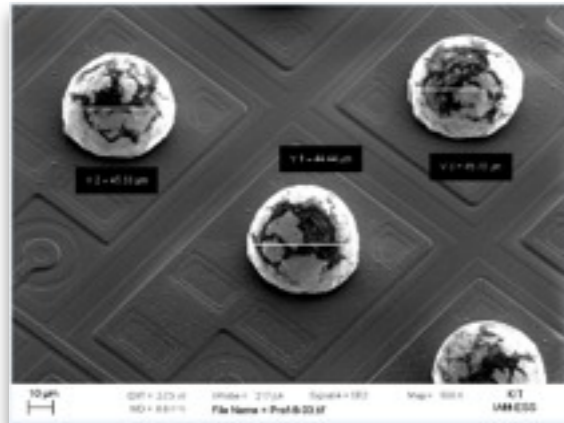
Thin monolithic detectors



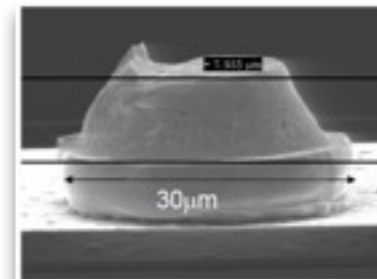
CCPD – Prototypes in AMS H18

Bumping technologies

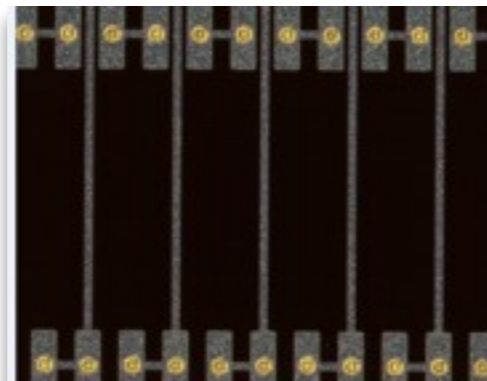
- Micro contacts on silicon for flip-chip interconnects
- Au stud bumping: $d=30\ \mu\text{m}$, UBM-less
- SAC Solder balls (PPS: Precoat by Powder Sheet): $d=10-80\ \mu\text{m}$
- Copper pillars: $d=15\ \mu\text{m}$



40 μm SAC ball after reflow



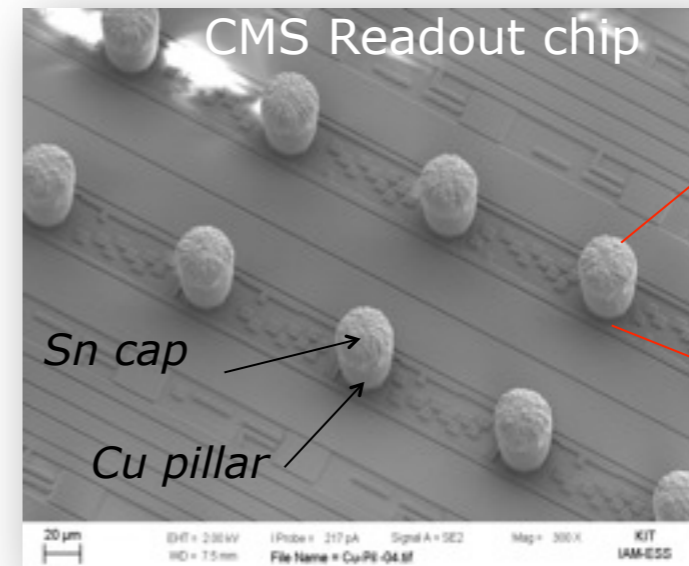
30 μm Au-Stud Bump



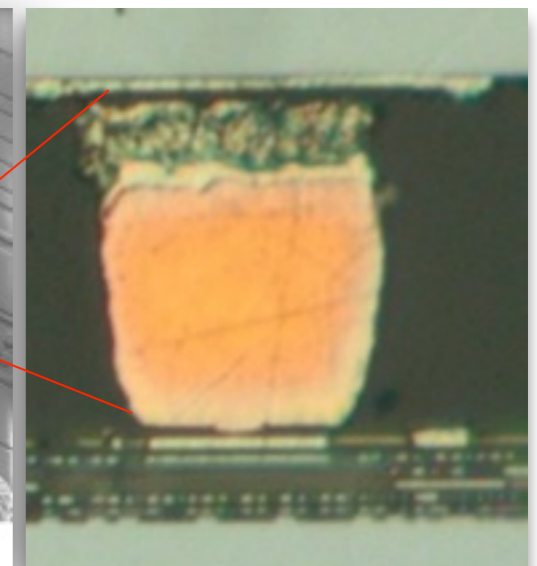
30 μm Au-Stud Bump on sensor dummy



SAC powder after transfer



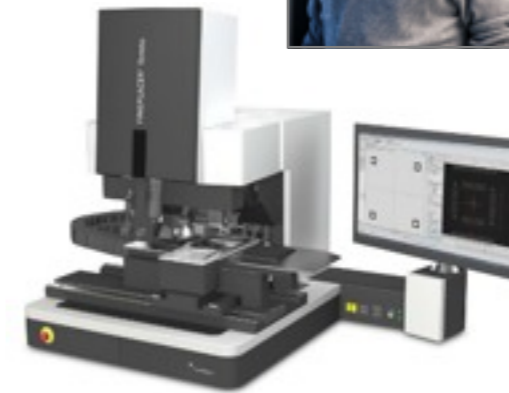
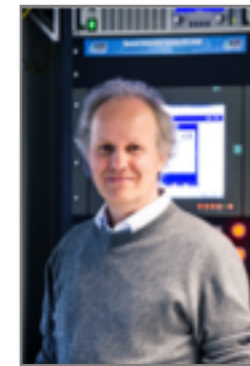
15 μm Cu-pillars on ROC-Chip



Cross section of Cu-pillar bonded sensor and chip

Flip chip technologies

- Dominant process for detector bare modules
- Interconnects shrinking from 30 μm to 10 μm
- High placement accuracy: $\pm 1 \mu\text{m}$
- Complex solder processes
- Quality control: production + functional tests



Flip chip die bonder

- accuracy: $\pm 1 \mu\text{m}$,
- speed: ~ 60 dies/h

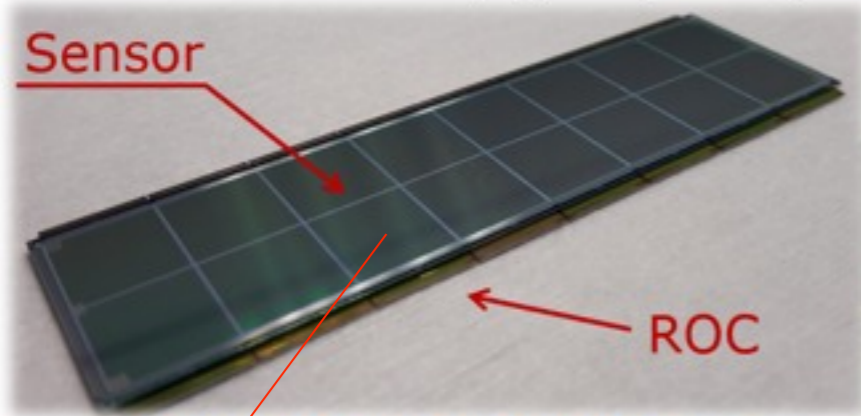


Multi-chip die bonder

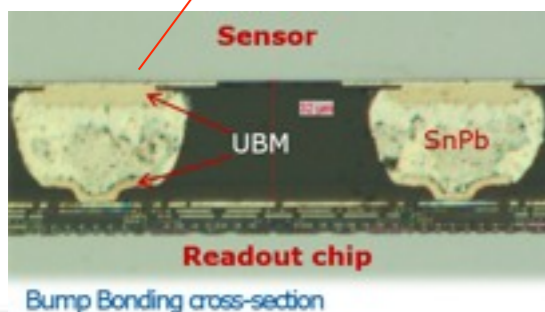
- $\pm 10 \mu\text{m}$
- ~ 1000 dies/h

Assembled bare module

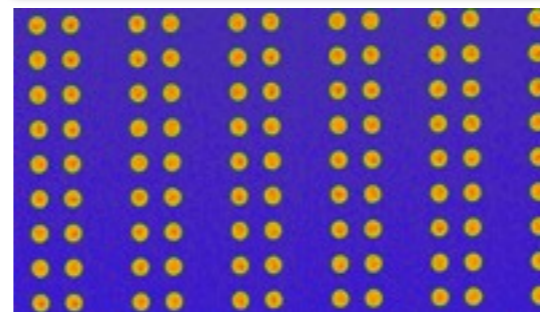
CMS Pixel detector (upgrade phase I)



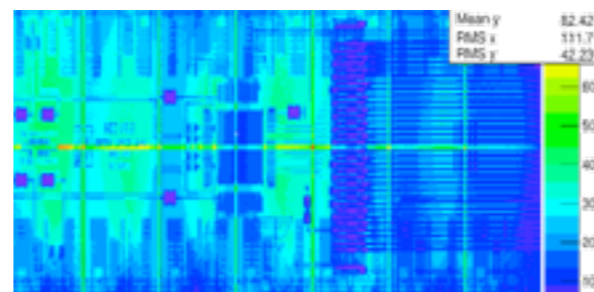
16 ReadOut Chips (ROC) \rightarrow 66560 pixels



Quality control



Micro-X-ray radiography
 \rightarrow void free interconnects



X-ray Bare Module Test



Vacuum reflow process with formic acid option

Silicon detector production center

- Successful production of 25% of the CMS pixel detector
- Production facility of the STS for the CBM experiment at FAIR/GSI



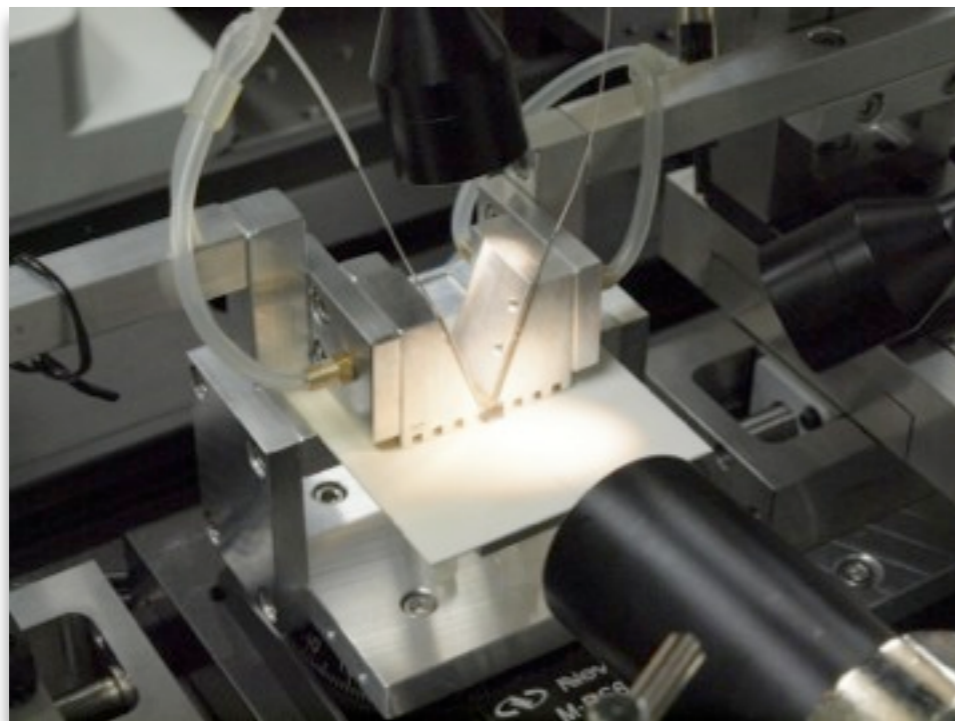
- Production of the CMS silicon tracker for HL-LHC



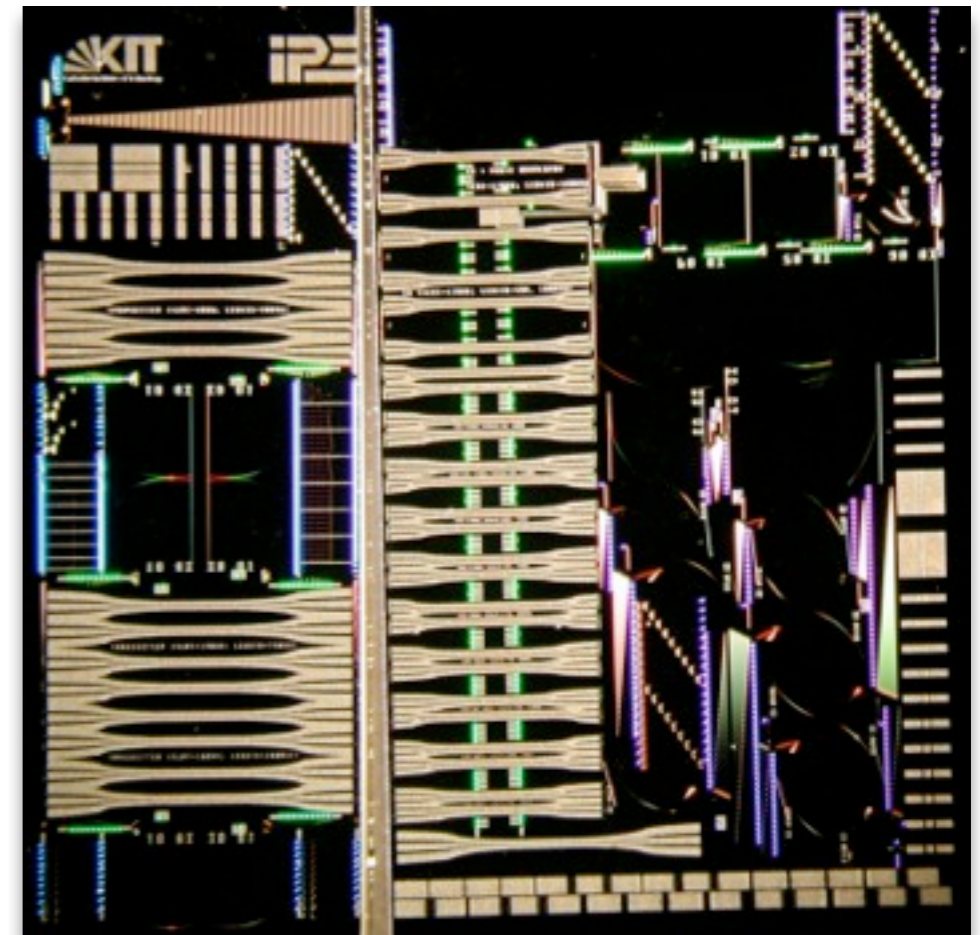
Tb/s optical data transmission



- Device design and simulation
- Monolithically integrated WDM systems
- FPGA algorithms for complex modulation formats
- CMOS compatible
- 160 Gbit/s in the near future
- Up to 5 Tbit/s projected



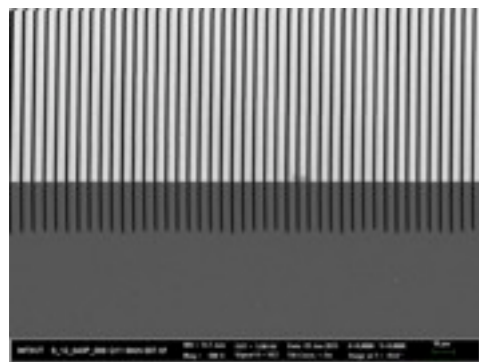
Fiber-chip-coupling experiments



Latest photonic chips with modulators, Echelle gratings, and 4 channel WDM systems

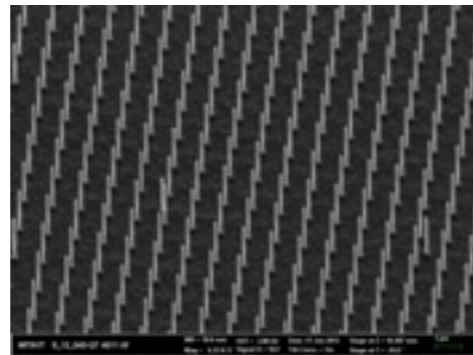
Research Infrastructure: Karlsruhe Nano Micro Facility

KNMF Example

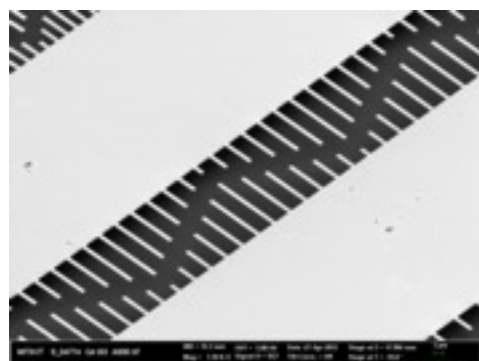


Deep etched silicon gratings

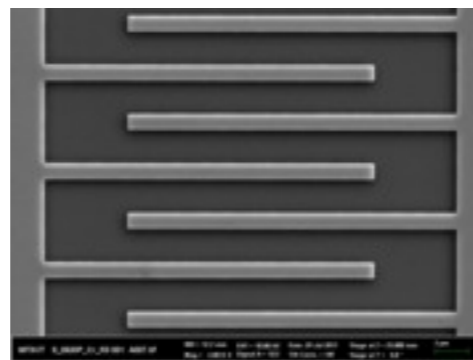
Silicon nanopillars with high aspect ratio



Freestanding cantilevers in silicon



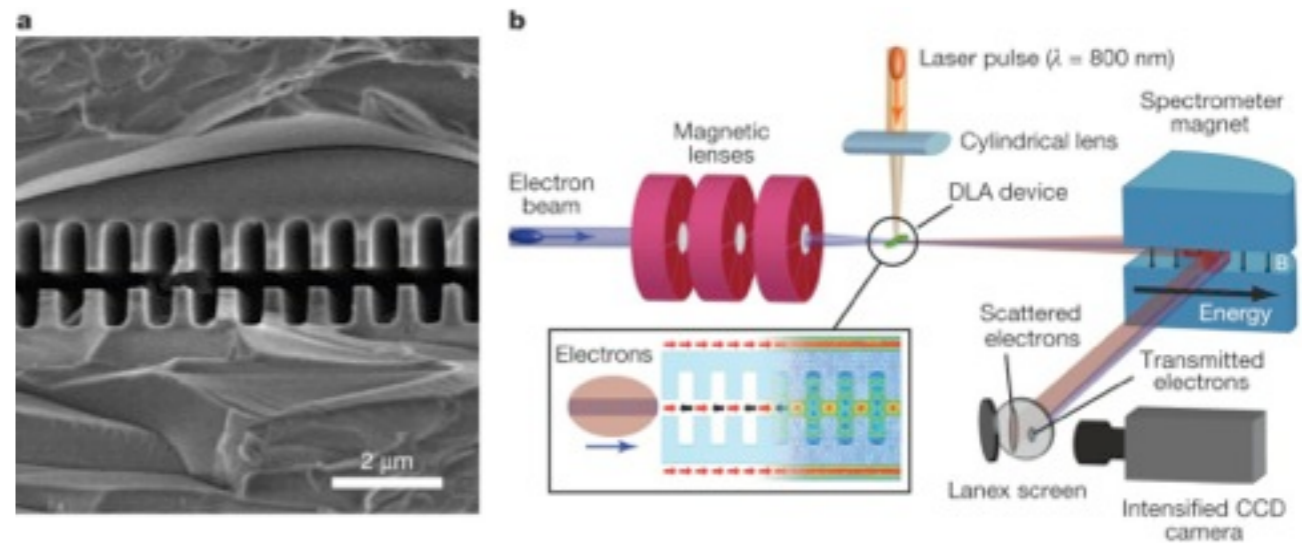
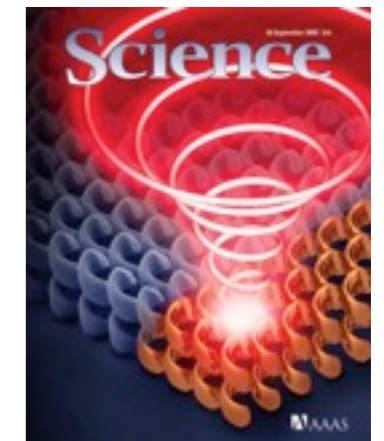
Cantilever structures in chromium



Center for Functional Nanostructures

- Metamaterials
- Artificial Materials
- Photonic Bandgap PBG Materials
- Engineered Crystals
- Multilayer Dielectrics

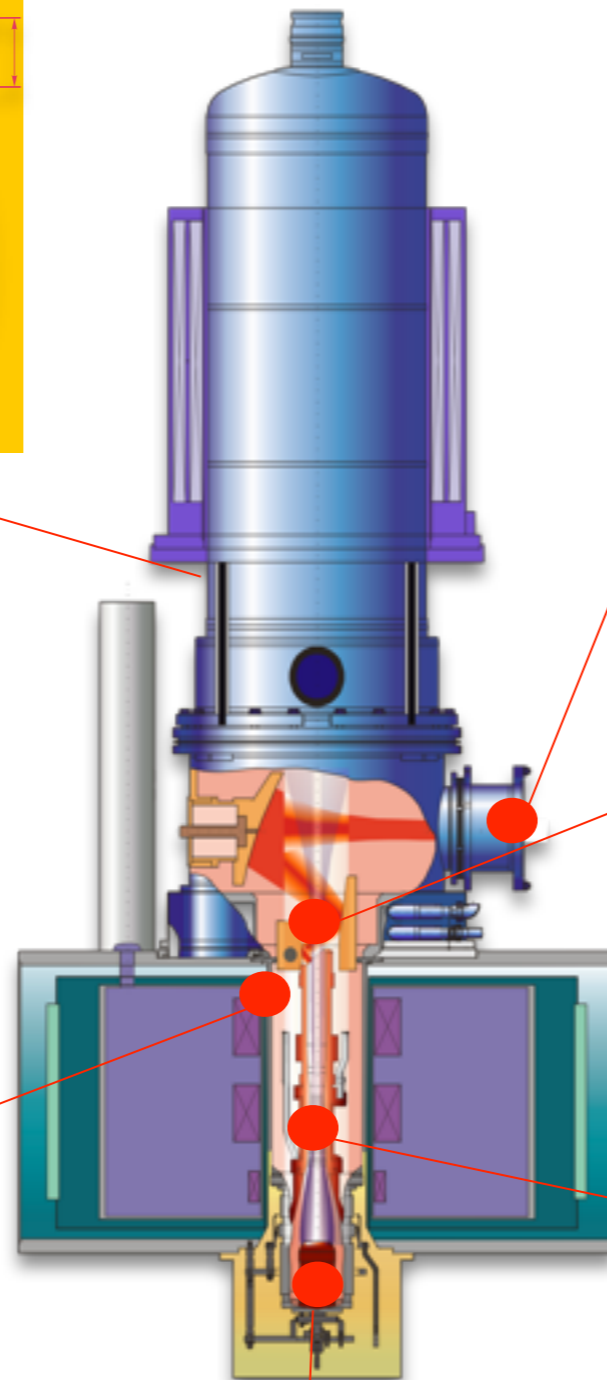
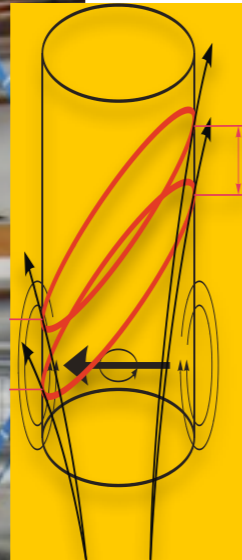
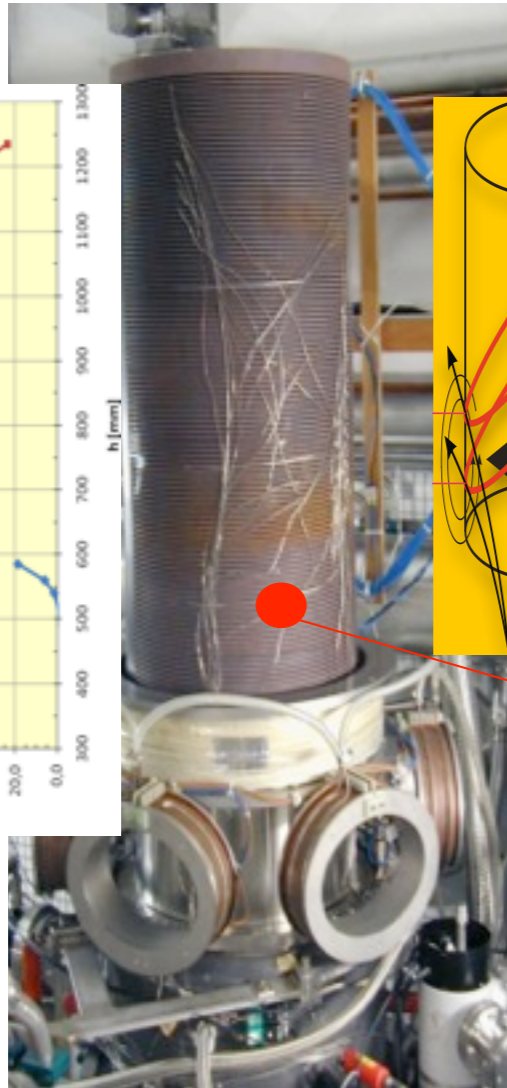
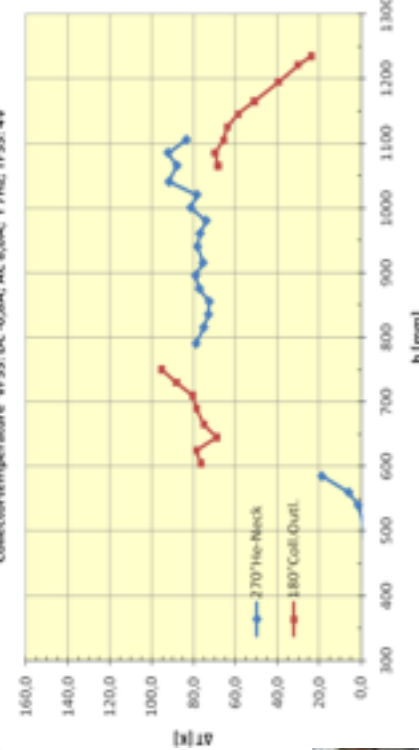
Manipulation of electromagnetic waves with materials



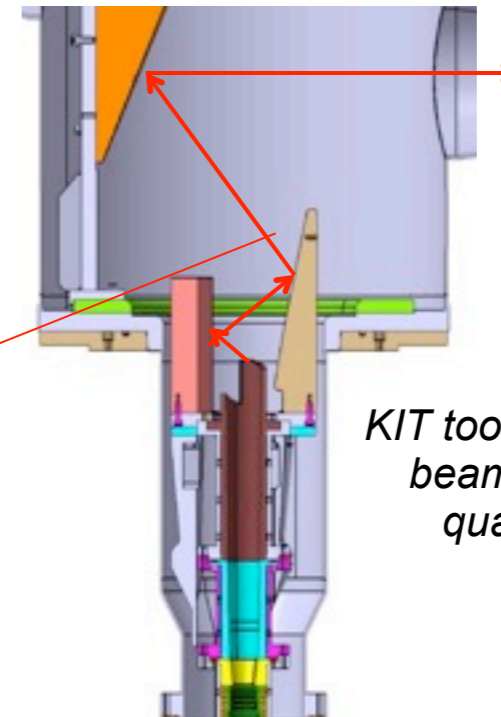
E.A. Peralta et al. Nature 503, 91-94 (2013)

KIT Electron Vacuum Tube (Gyrotron) Development

Collectortemperature VFSS:DC-0.8A; AC:0.04; F:7Hz; TFSS:4V



CVD Diamond Brewster-angle window technology (KIT-IAM, *Element Six / Diamond Materials*)

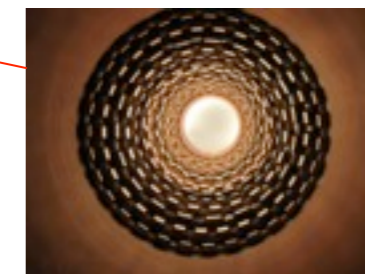


KIT tools and concepts for RF beam transformation and quasi-optical systems

Electron-optics systems for collectors operating at MW levels (IPP/KIT patent: TVSS)



thermo-mechanical designs Of highly loaded structures



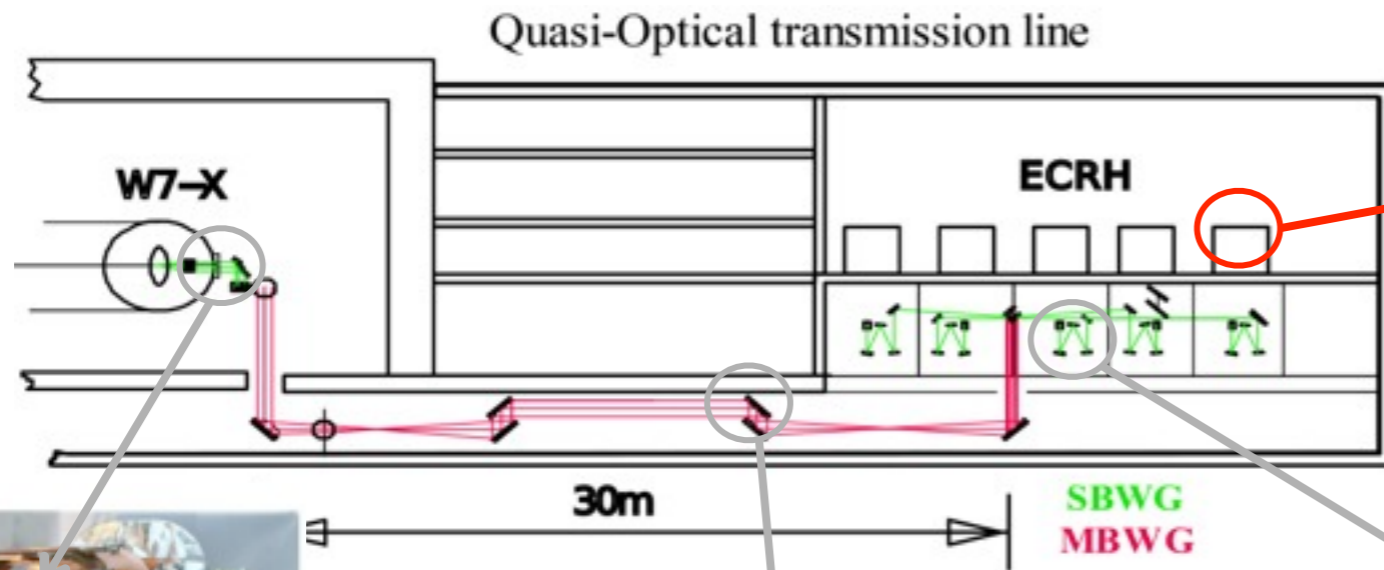
KIT tools and concepts for highly overmoded structures



ECRH for Stellarator W7-X

KIT Project PMW

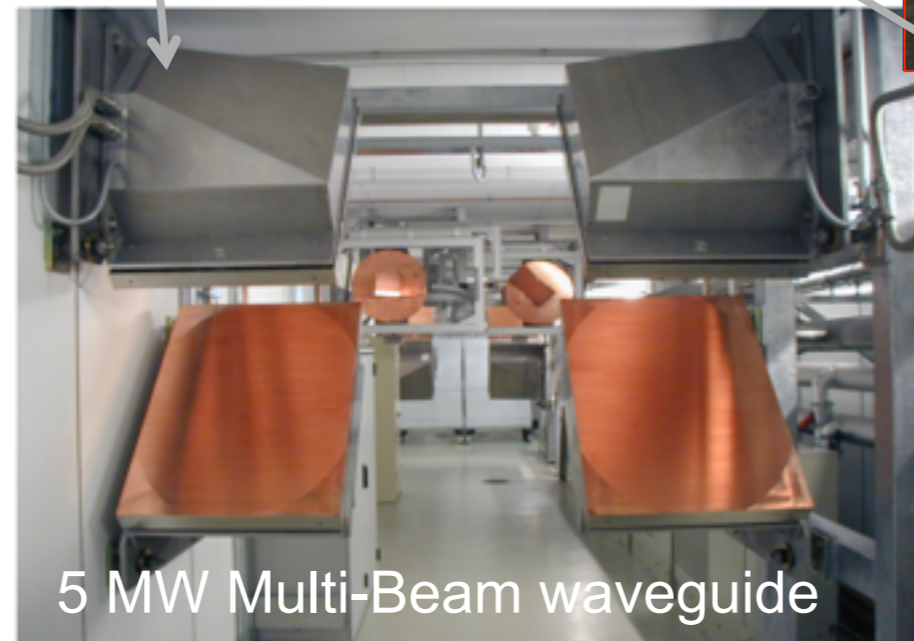
10x 140 GHz 1 MW CW Gyrotron + SC magnets
+ HV modulators + transmission lines + launchers



gyrotron installation at IPP Greifswald



In-vessel components



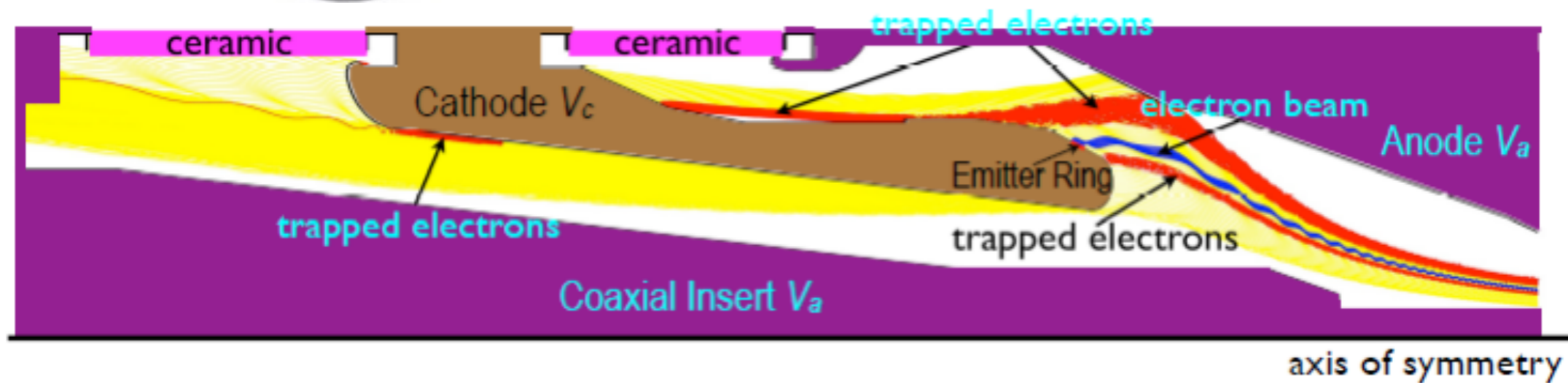
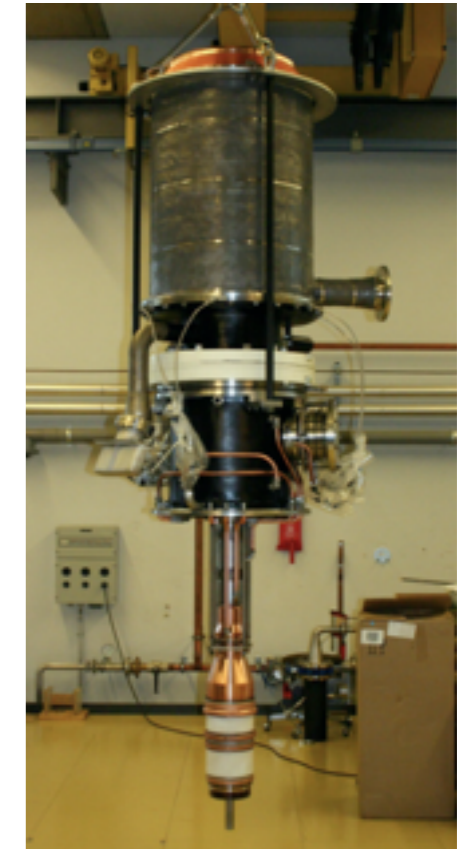
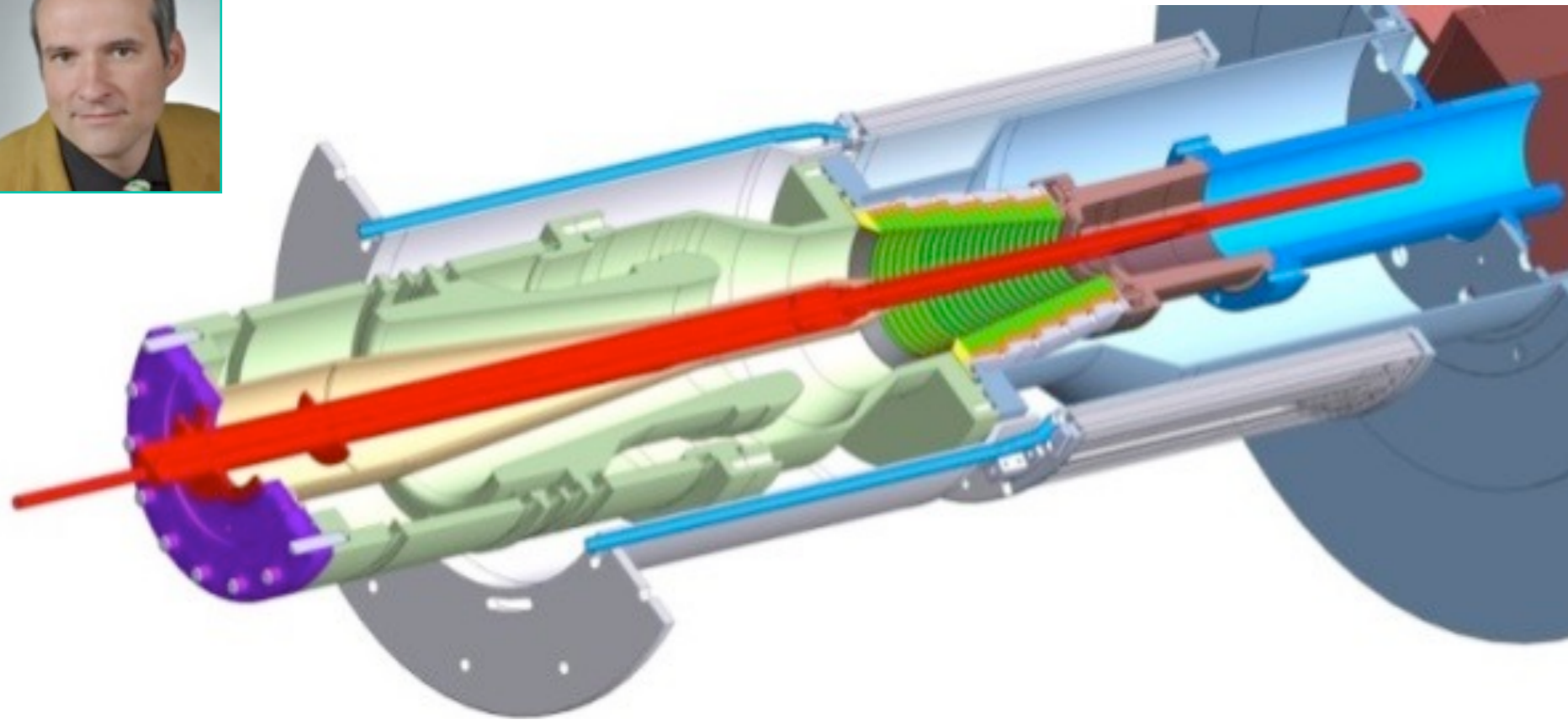
5 MW Multi-Beam waveguide



Single Beam Modules + Beam Combining Optics

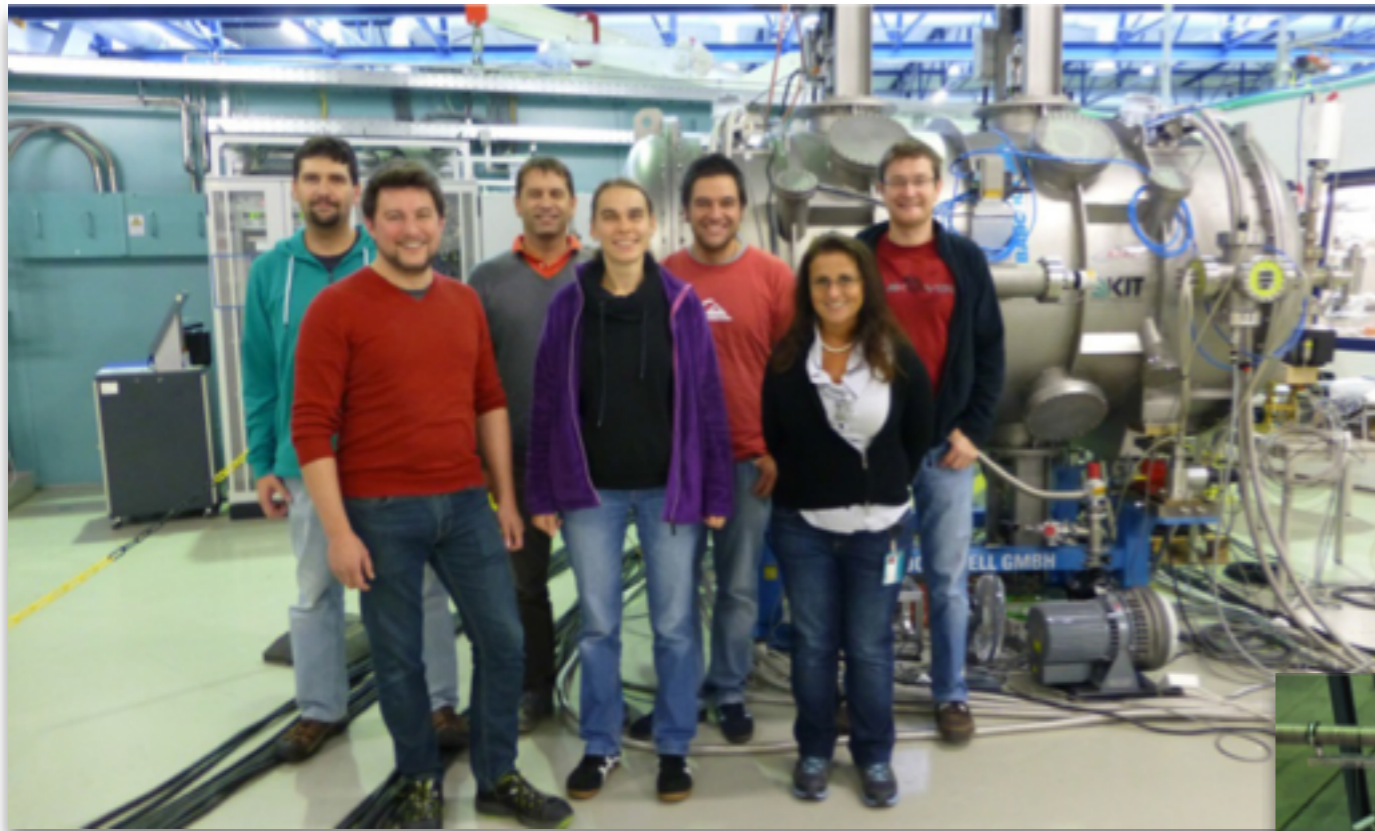


Advanced Electron Gun Design Concepts and Tools (Thermionic Emission)



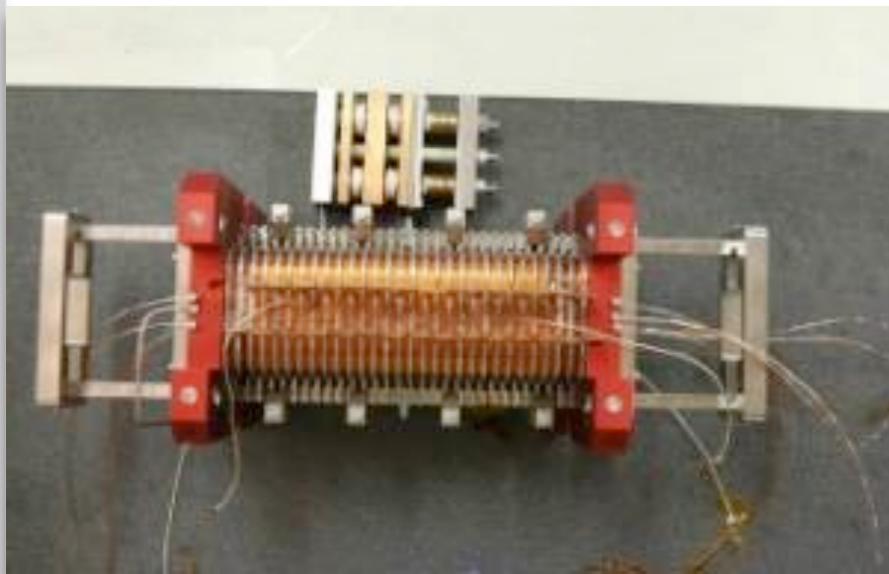
Pagonakis et al., "An Additional Criterion for Gyrotron Gun Design", Oral Presentation, 37th ICOPS, USA, 2010

Development & beam tests of superconducting insertion devices

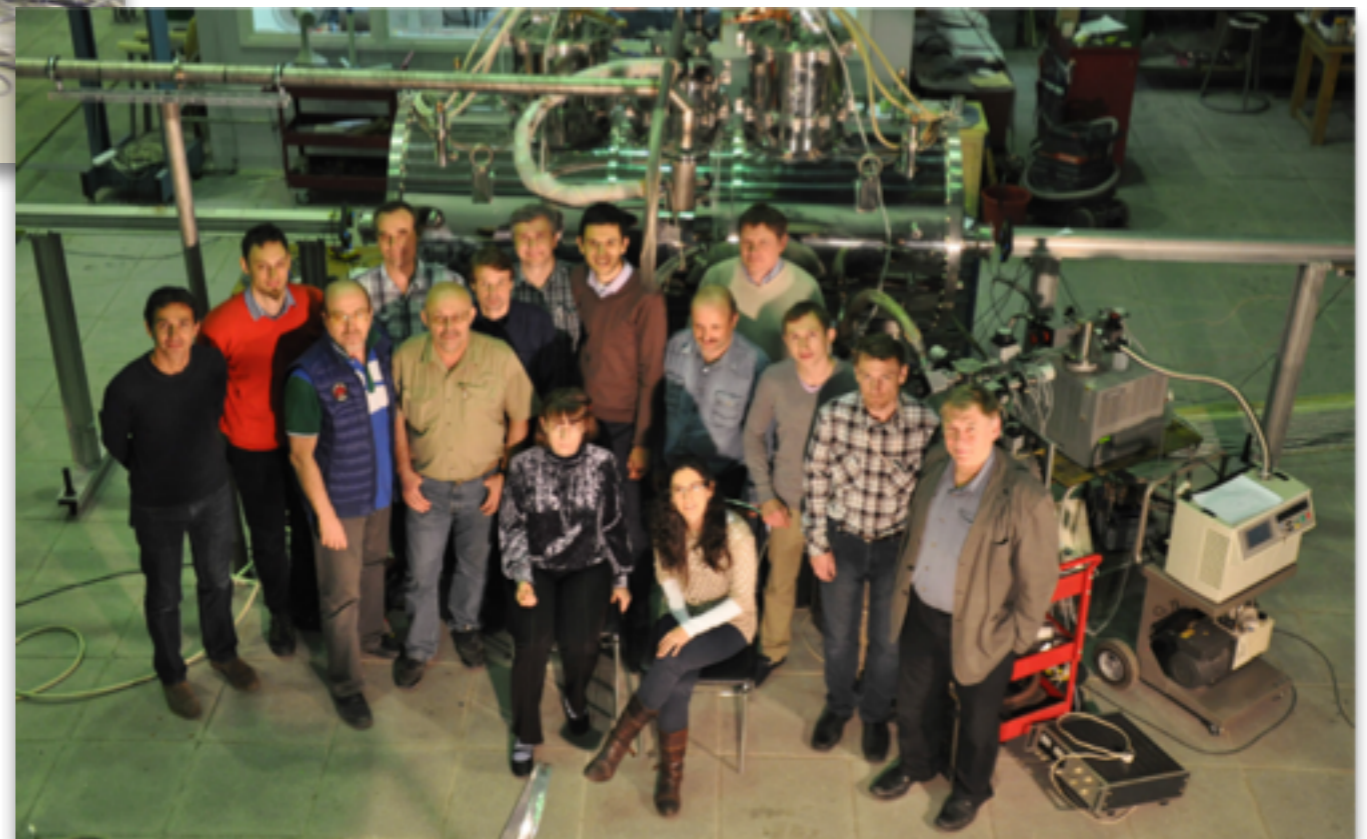


SCU15 at KIT before installation

- experienced teams
- successful collaborations with CERN and BINP (CLIC-DW) and with industry (Babcock Noell SCU15)



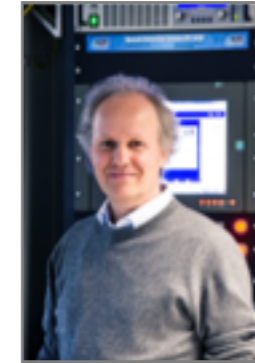
SCU20 Mockup



Damping wiggler test in Novosibirsk

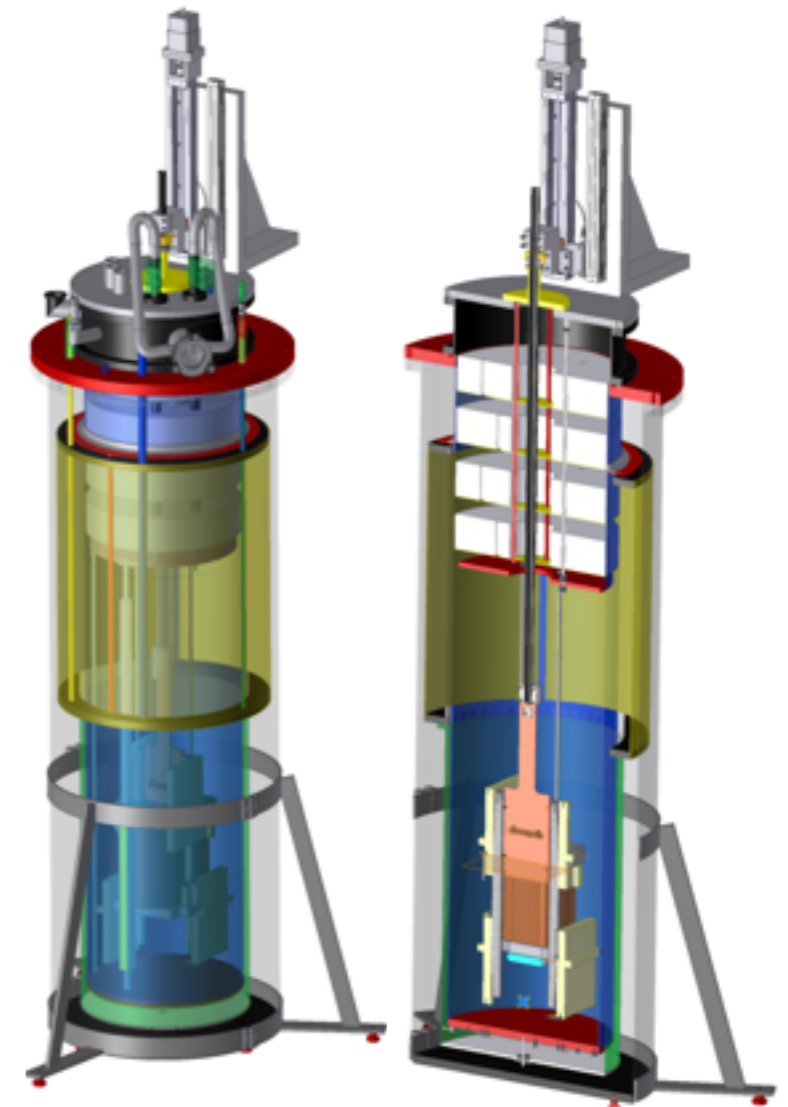
Quench detection

- Turn-key quench detection system with custom FPGA-based electronic detector design (EU patent pending)
- Combines reliable specific analogue signal processing (differential detector input) with computer-based detector parametrization, quench event data logging and operation diagnostics
- The KIT quench detection system is a modular and scalable device with complete soft-ware package “*QVision*” to operate up to 65536 detectors
- In operation or commissioning at W7-X, KATRIN, HZB, ANKA, GSI, TOSKA

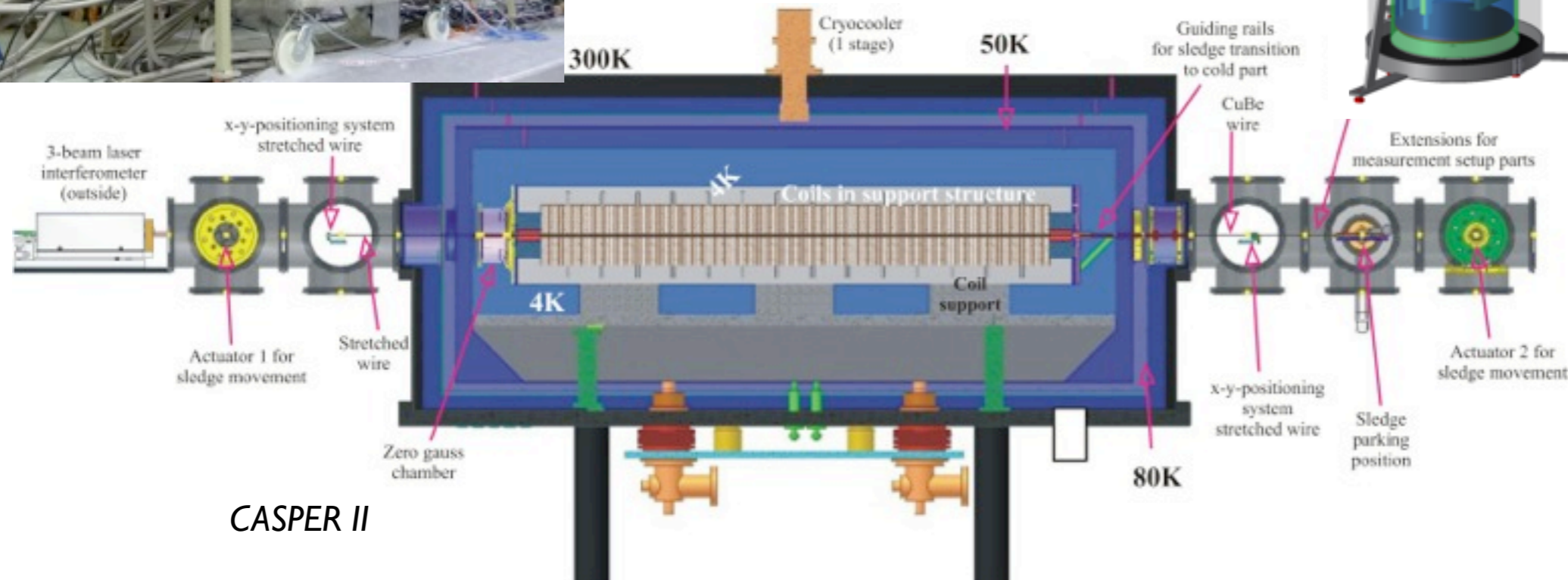


Superconducting ID characterisation

- CASPER I: short (30 cm) coils in LHe
- CASPER II: up to 2 m coils in conduction cooling

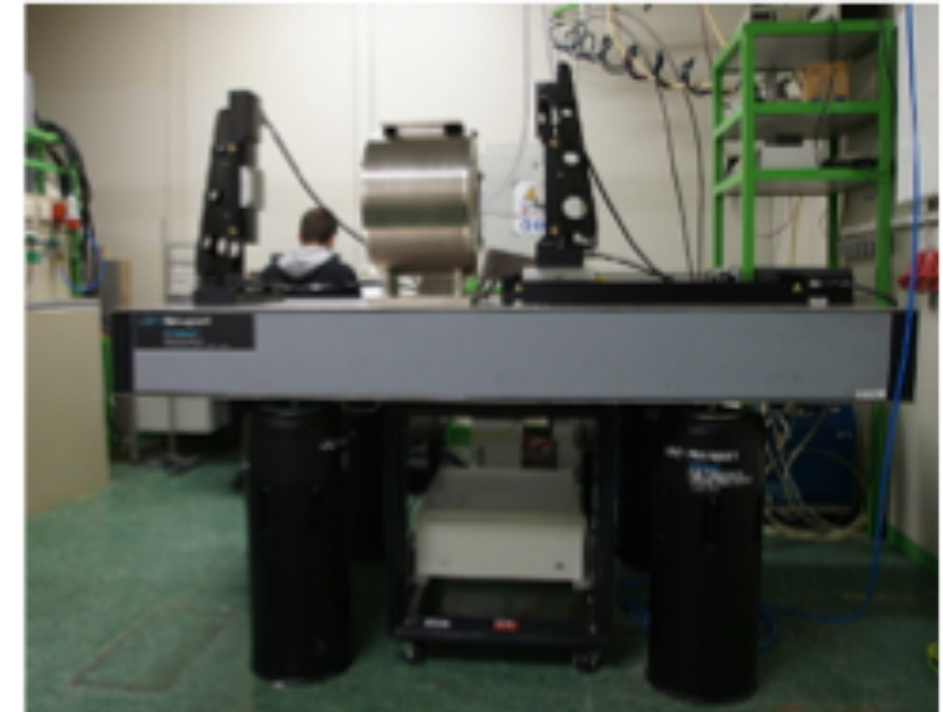
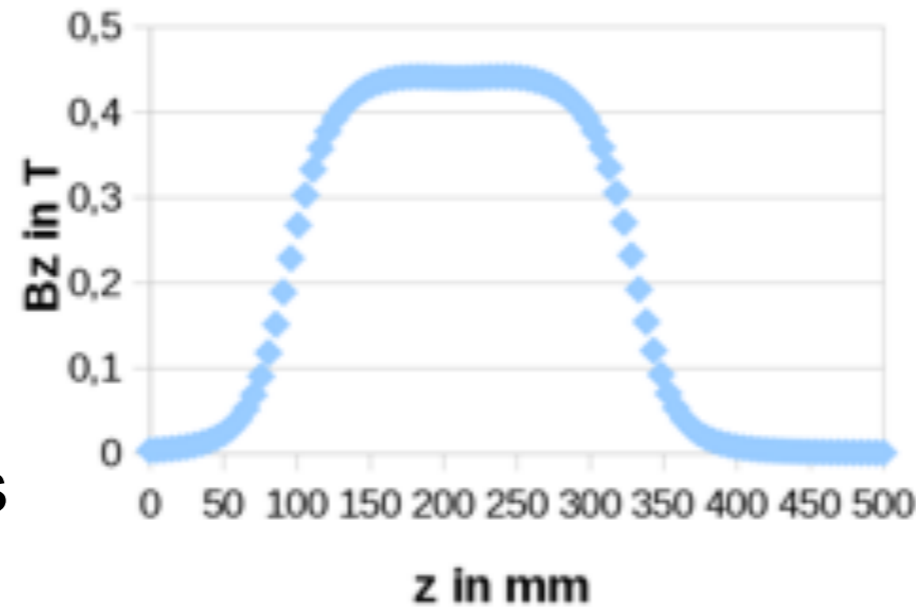


CASPER I

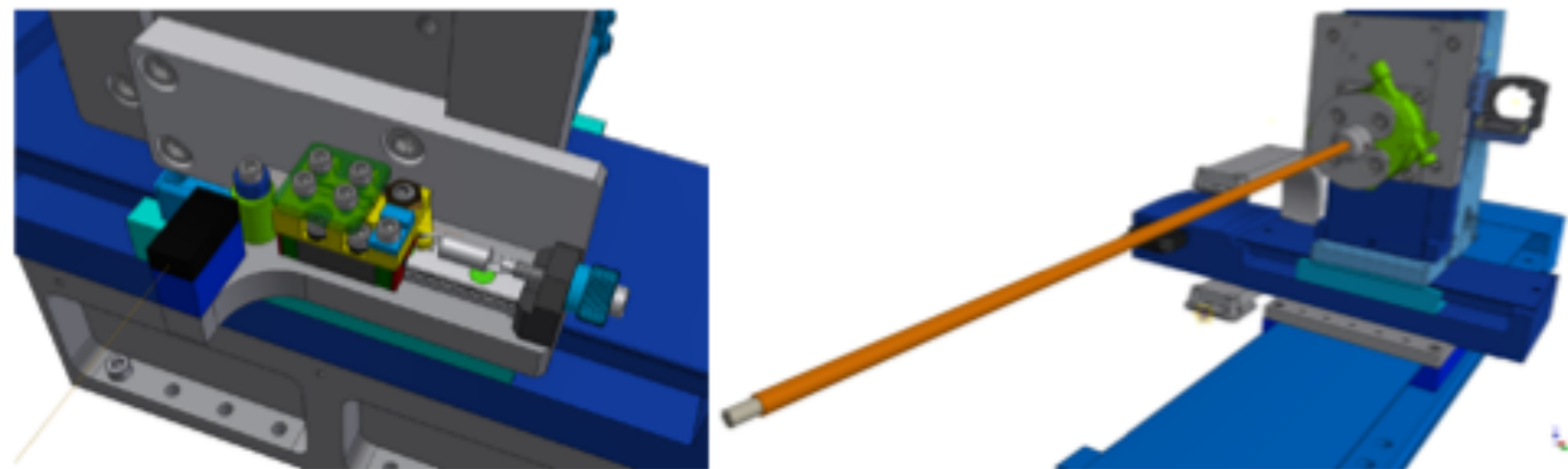


Conventional magnet fabrication & characterisation

- Magnetic characterisation of various magnets
- Techniques: Hall-Probe and Stretched-wire
- In-house winding of conventional and super-conducting coils



Magnet test bench

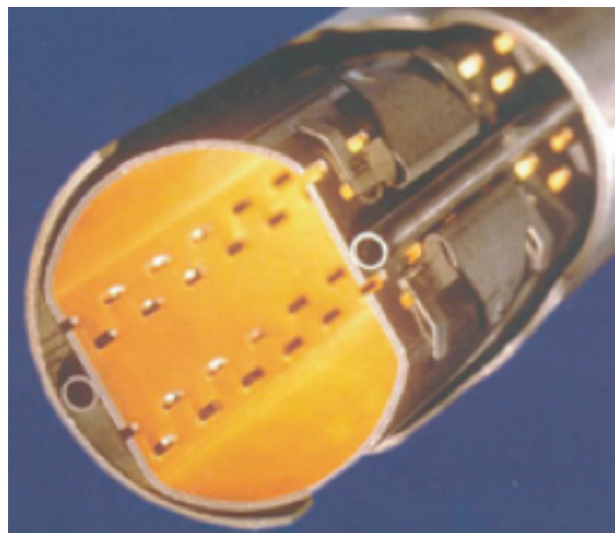


Diagnostics of cold surfaces

- COLDDIAG set-up to analyse beam heat load on cryogenic surfaces; Experiments at DIAMOND
- EuroCirCol: test of FCC vacuum chamber prototype

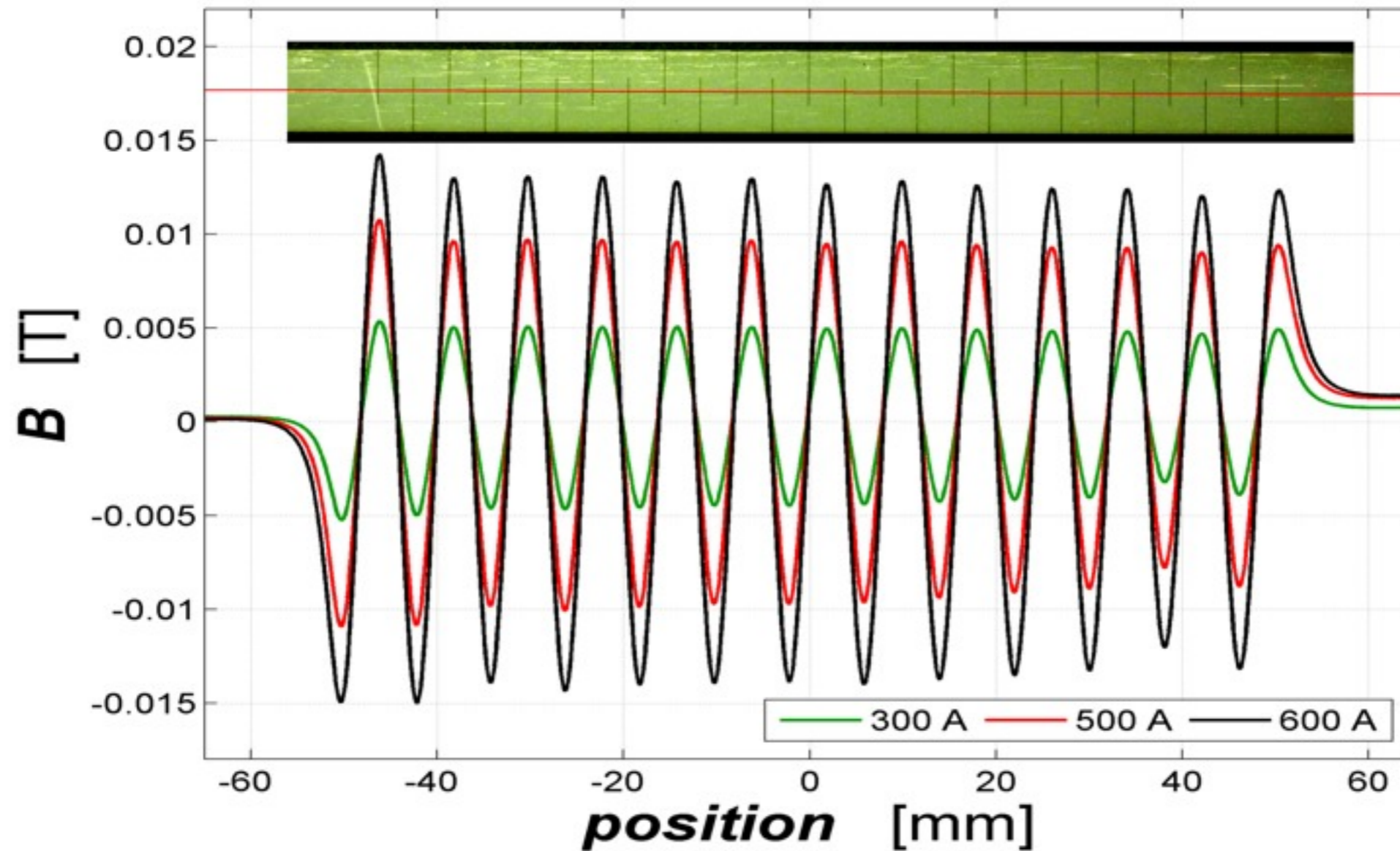


COLDDIAG at DIAMOND



HTS developments

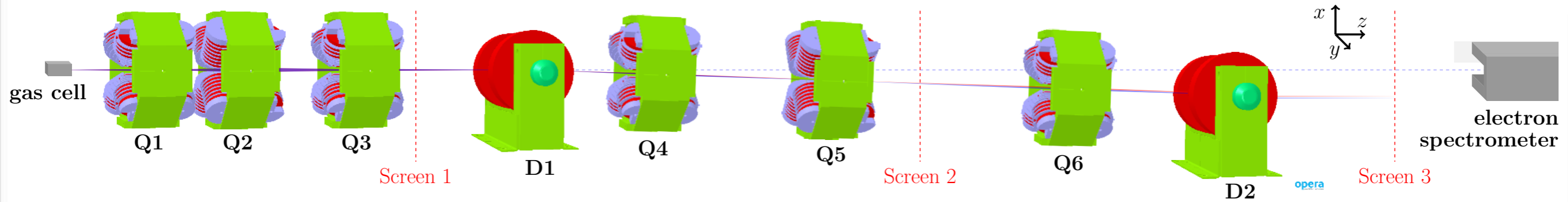
- HTS tape stacked undulator



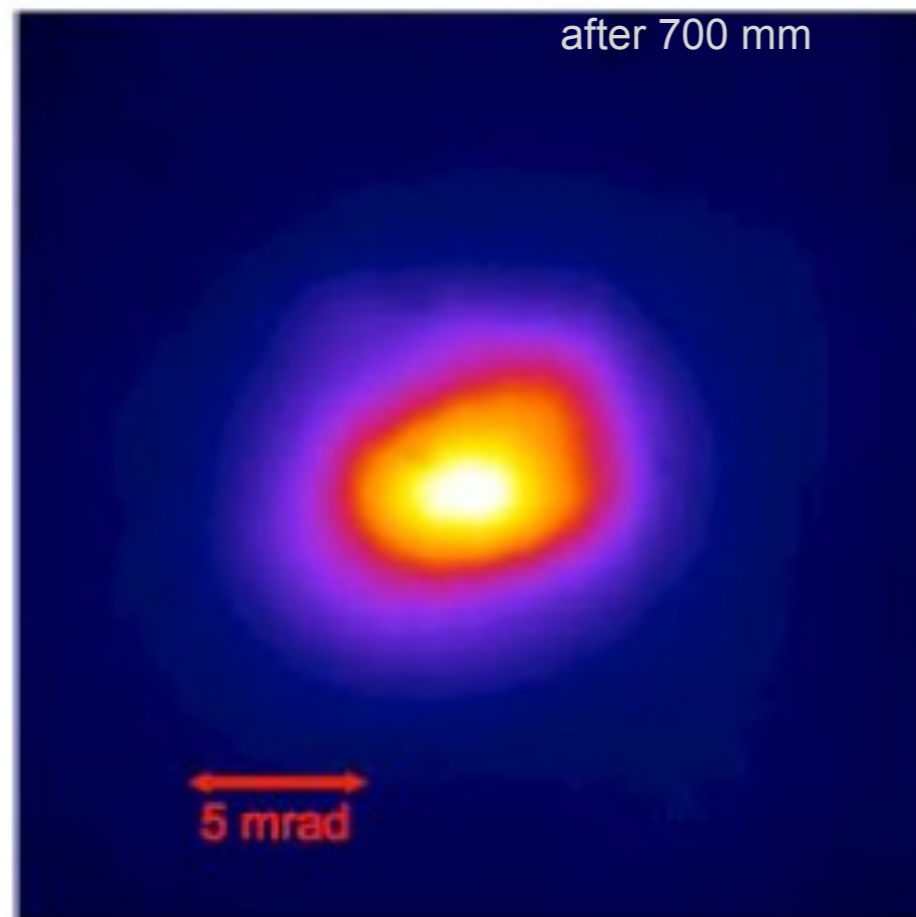
*T. Holubek et al., IEEE Trans.
on Appl. Supercond.
4602204, 23-3 (2013)*

*Measured magnetic field
profile of a HTS stacked undulator*

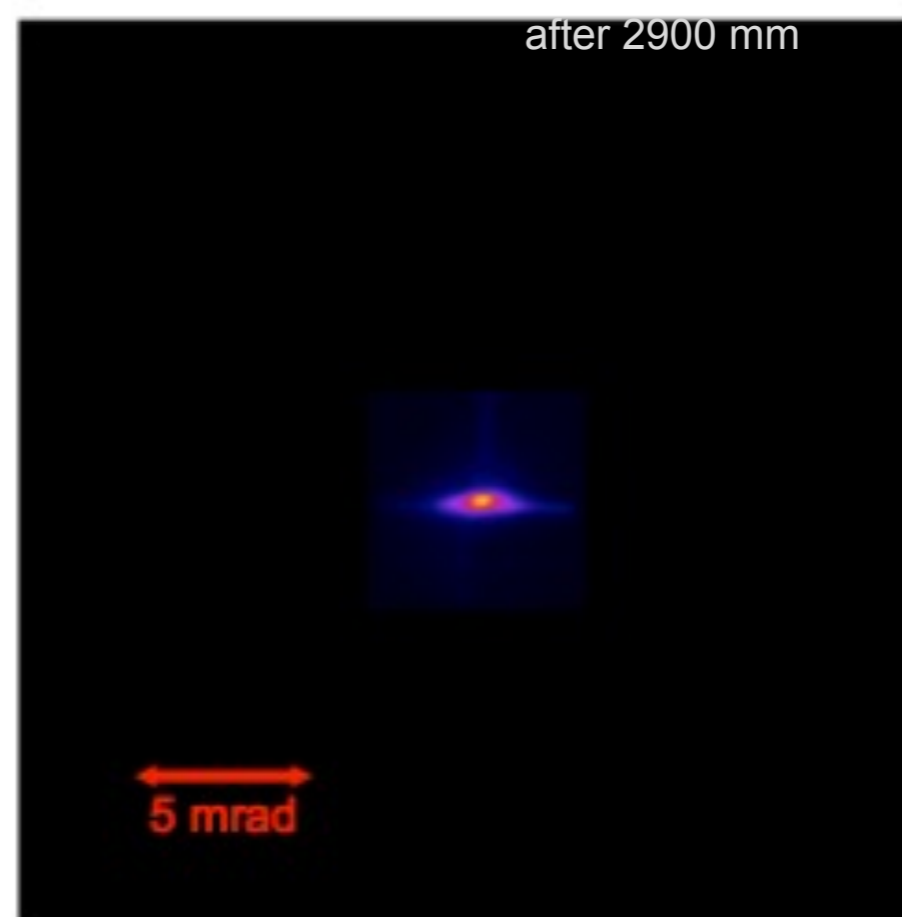
Beam transport from the laser wakefield accelerator JETI to a SC transverse gradient undulator



Courtesy M. Kaluza (HI Jena), C. Widmann (KIT), et al.



without electron transport line



with electron transport line



C. Widmann et al., IPAC2015 MOPWA045

The ANKA synchrotron radiation facility

■ Normal operation:

■ Energy 2.5 GeV

■ Current 200 mA

■ **Bunch length** $\sigma \approx 45$ ps

■ Low Alpha mode:

■ Energy 0.8 - 1.6 GeV

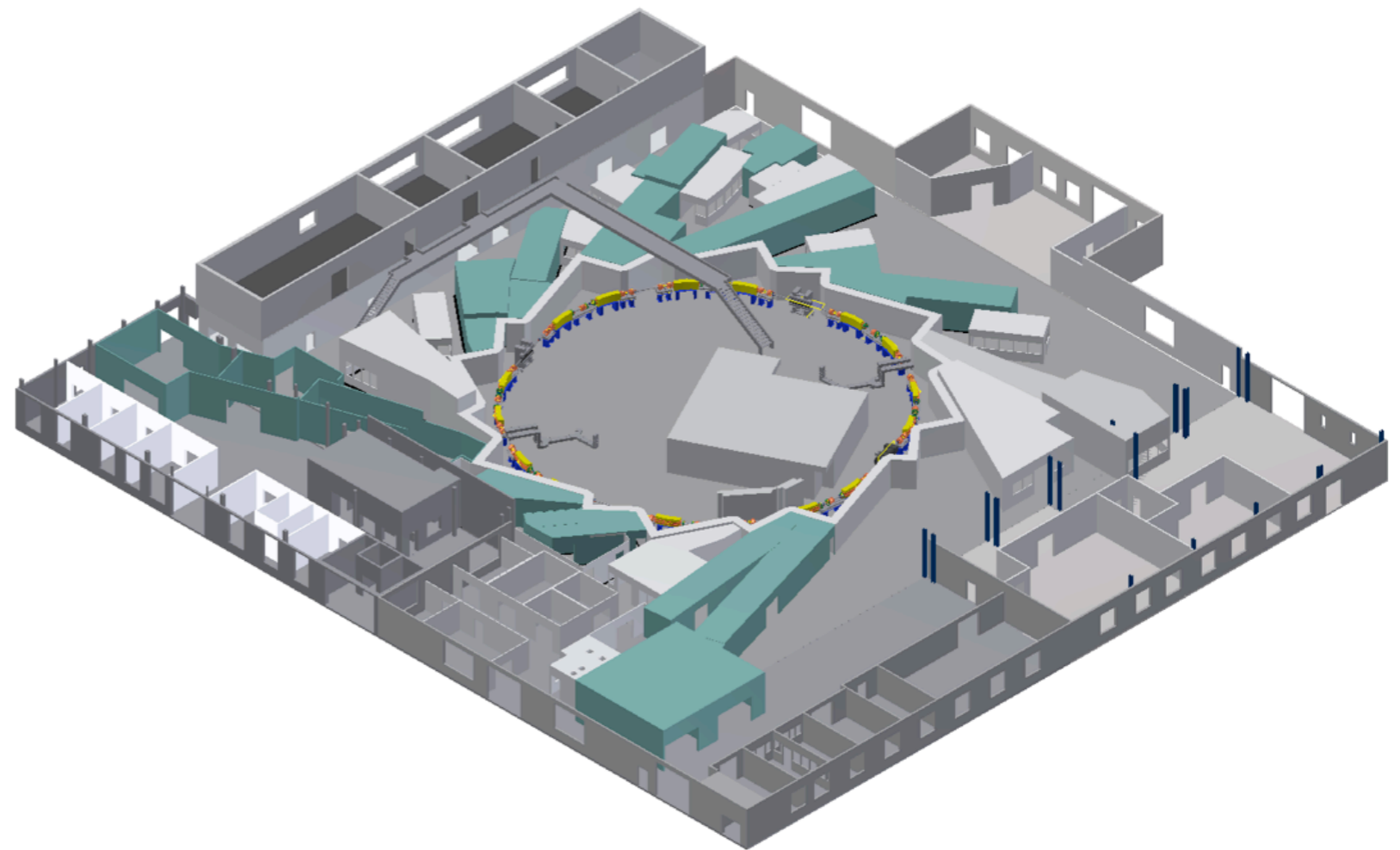
■ Current ≈ 70 mA

■ **Bunch length**
 $\sigma \approx 10$ ps down to 1-2 ps

■ **Coherent THz radiation**

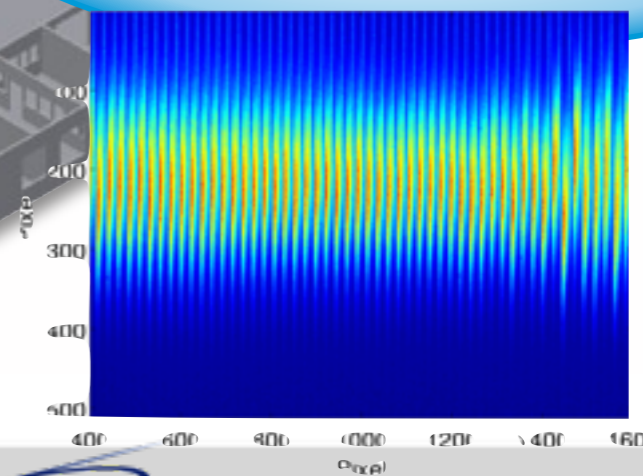
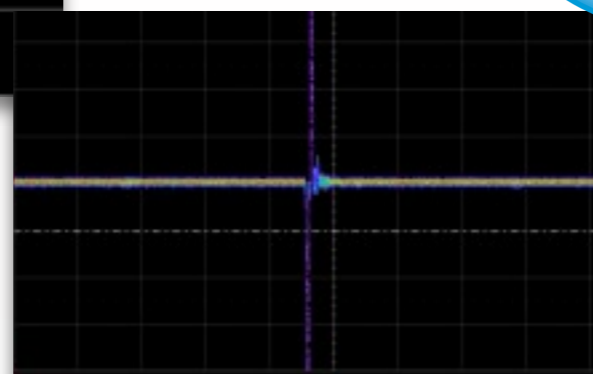
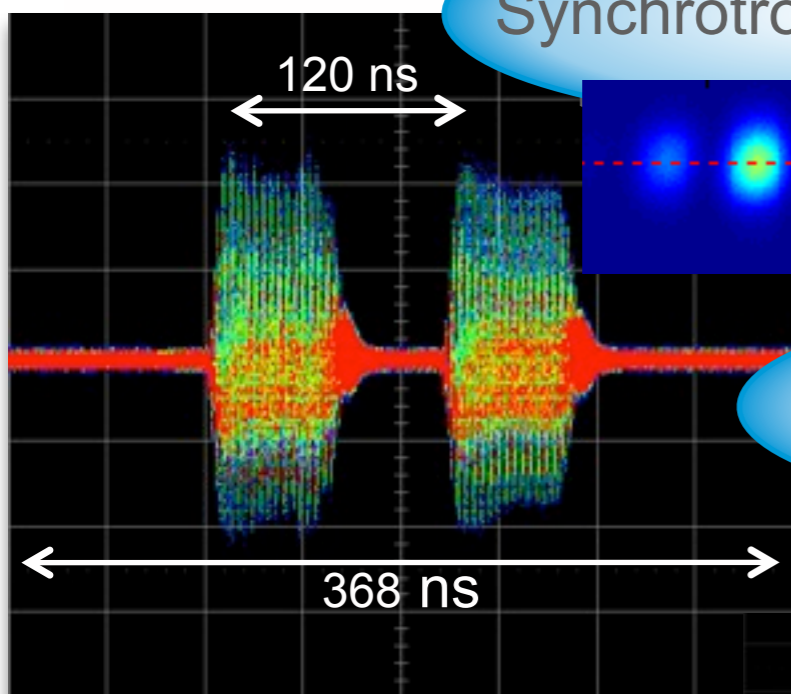
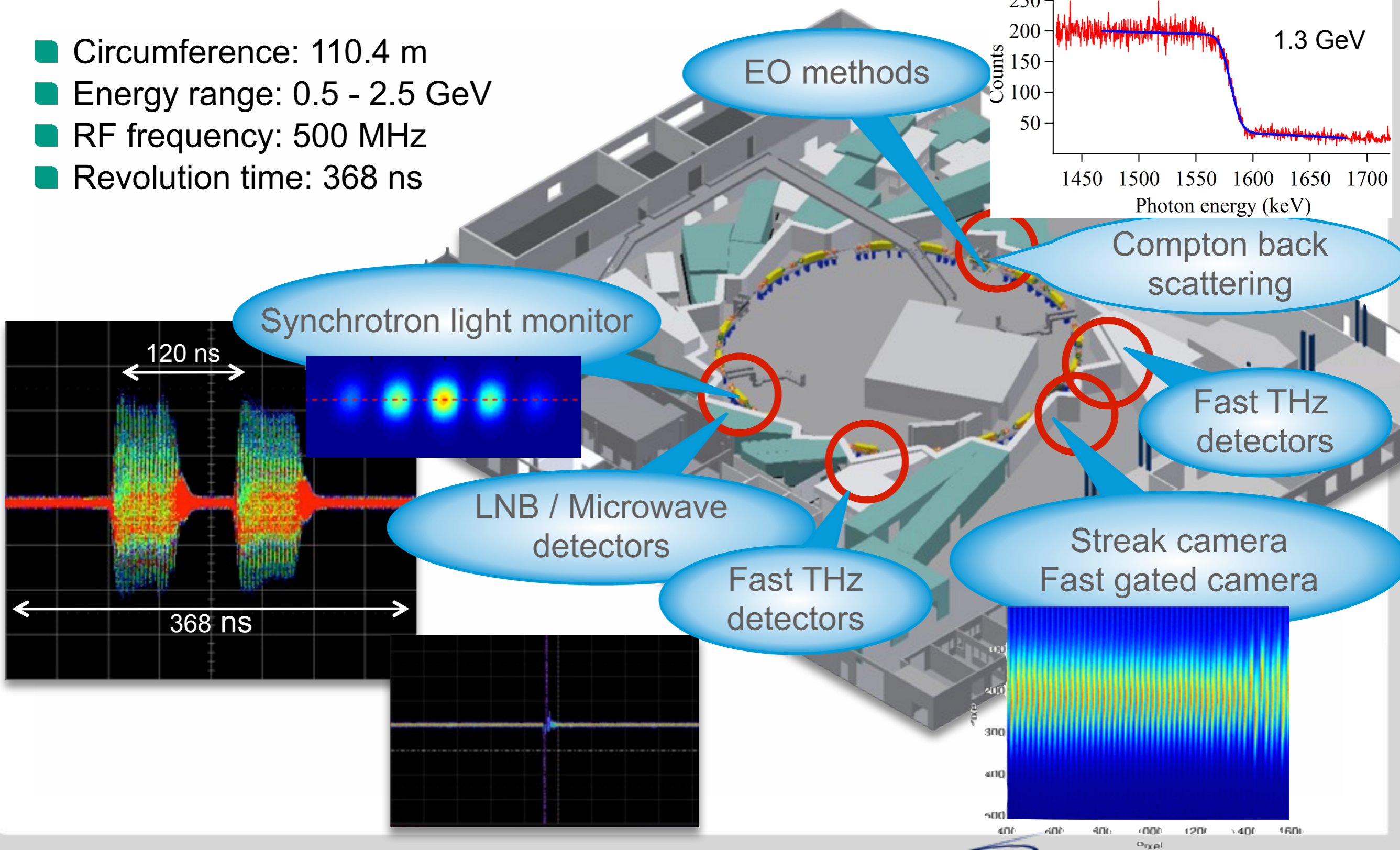
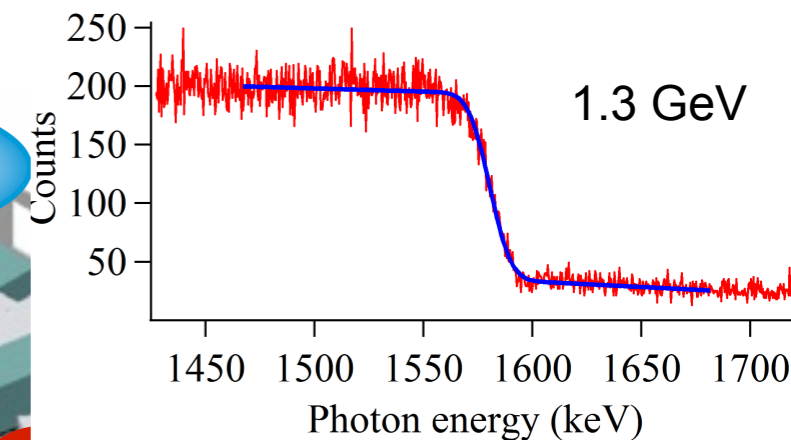
■ **Photon science facility and technology platform**

→ **new operation/usage strategy in preparation: open for R&D!**



The ANKA synchrotron radiation facility

- Circumference: 110.4 m
- Energy range: 0.5 - 2.5 GeV
- RF frequency: 500 MHz
- Revolution time: 368 ns



Short bunches: physics & phenomenology

■ CSR spectrum

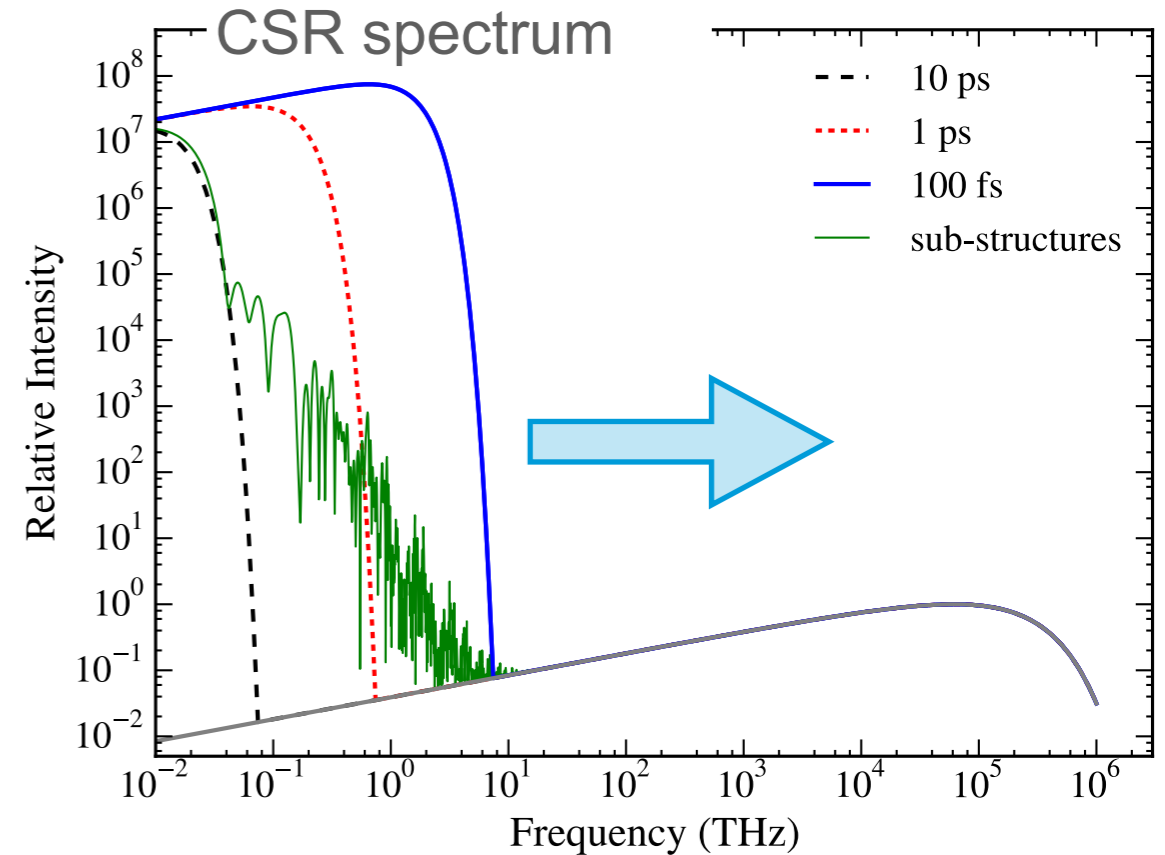
- high radiation power
- strong e.m. fields
- self-interactions

■ (μ -bunching) instabilities

- occur above a threshold current
- threshold depends on, e.g., RF voltage, vacuum chamber geometry, bending radius, but also on the filling pattern
- really short bunches only for low bunch currents

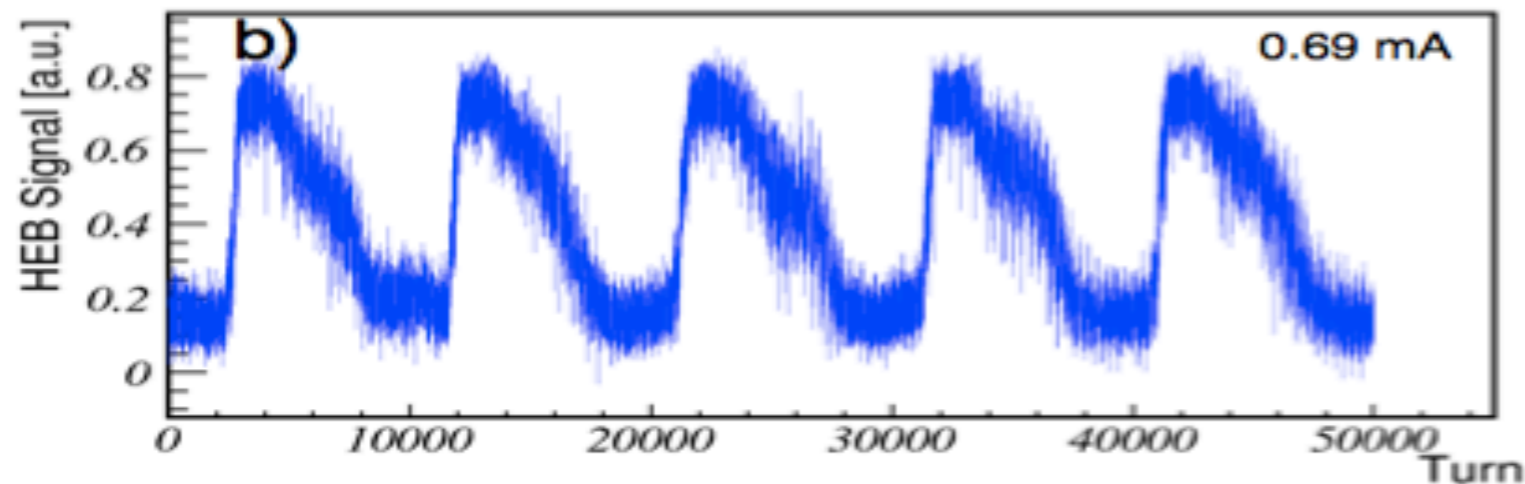
■ Key issues for short bunch diagnostics

- high resolution (ps) - high rate (500 MHz) - long term observation (secs - hrs)
- 2 categories:
 - indirect: *detection of coherent and incoherent radiation (microwave - vis)*
 - direct: *detection of bunch Coulomb fields*



μ -bunching instability

- Dynamic sub-structures lead to bursts in the THz signal -> signature

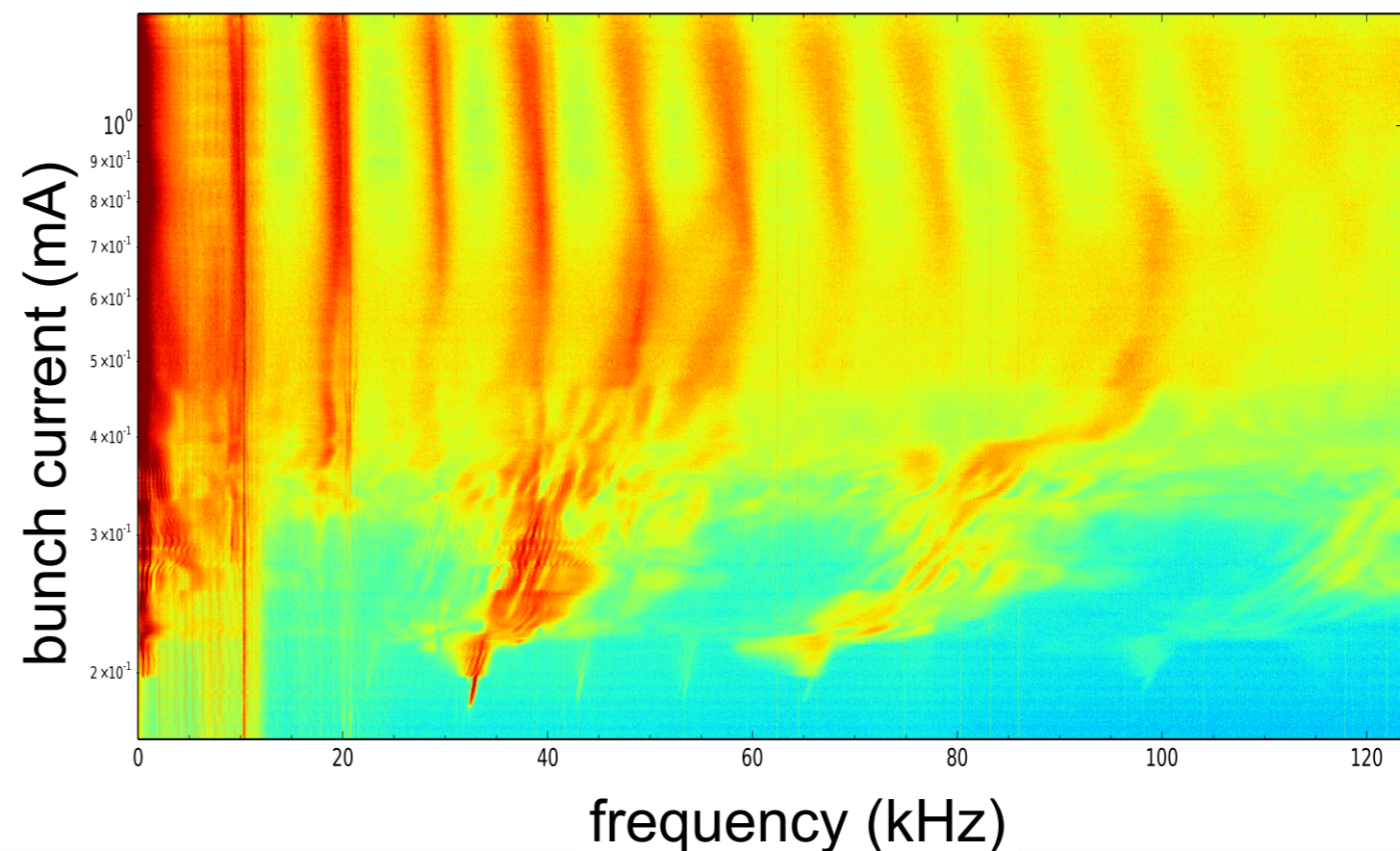


THz signal measured with an ultra-fast detector system

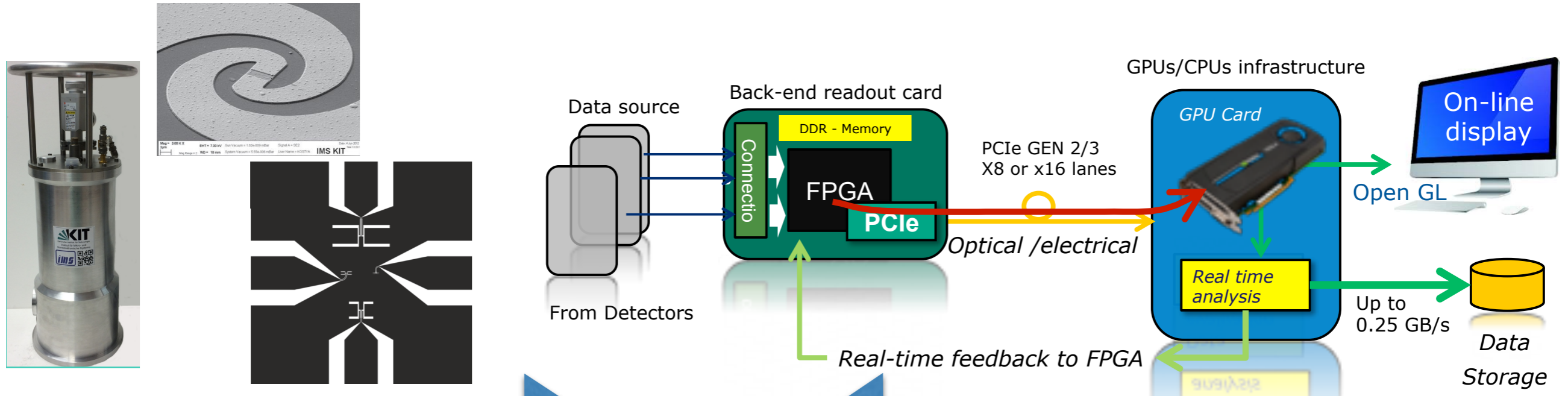
V. Judin et al., IPAC2010, WEPEA021

FFT of THz signal as a function of bunch current

V. Judin et al., IPAC 2014, MOPRO063



THz signal dynamics - development of detectors, readout & (online) analysis

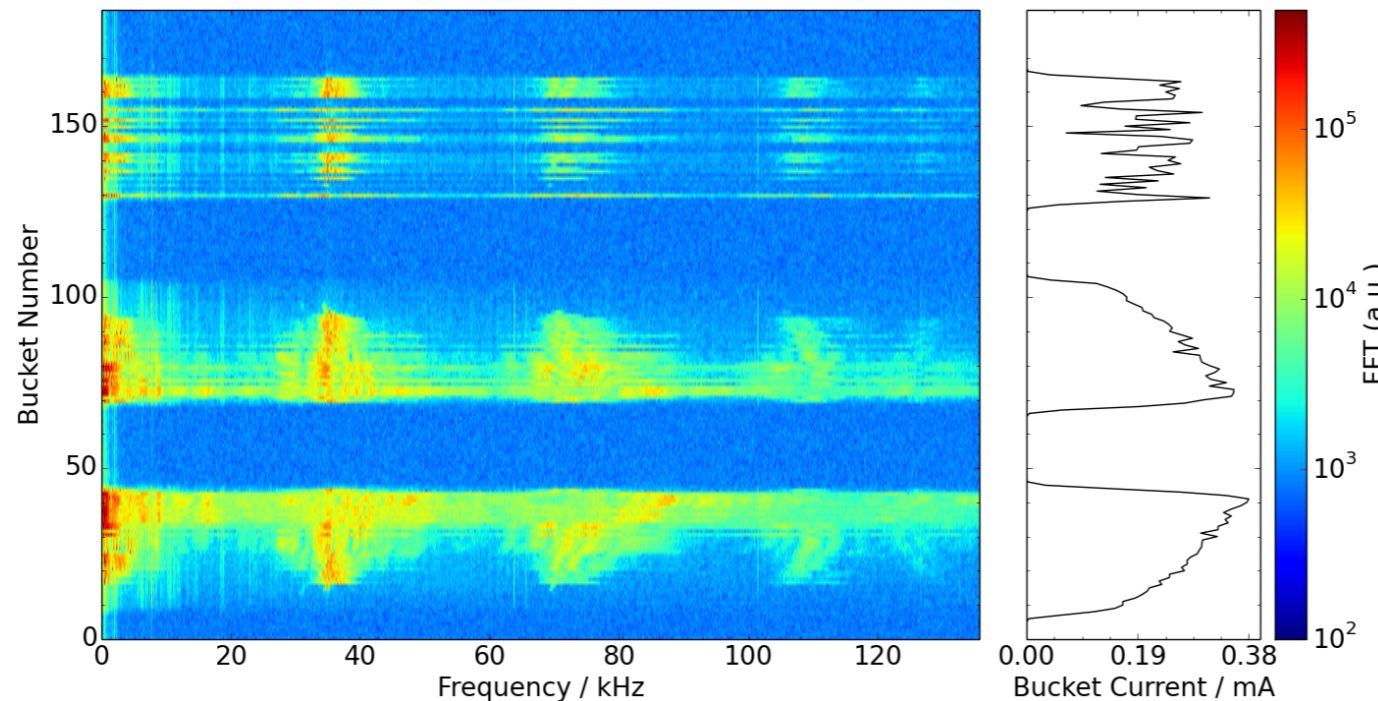


P. Thoma et al., Appl. Phys. Lett. 101, 142601 (2012)

A. Schmid et al., 3rd ARD ST3 Workshop (2015)

M. Caselle, et al., Journal of Instrumentation, 9(01):C01024 (2014)

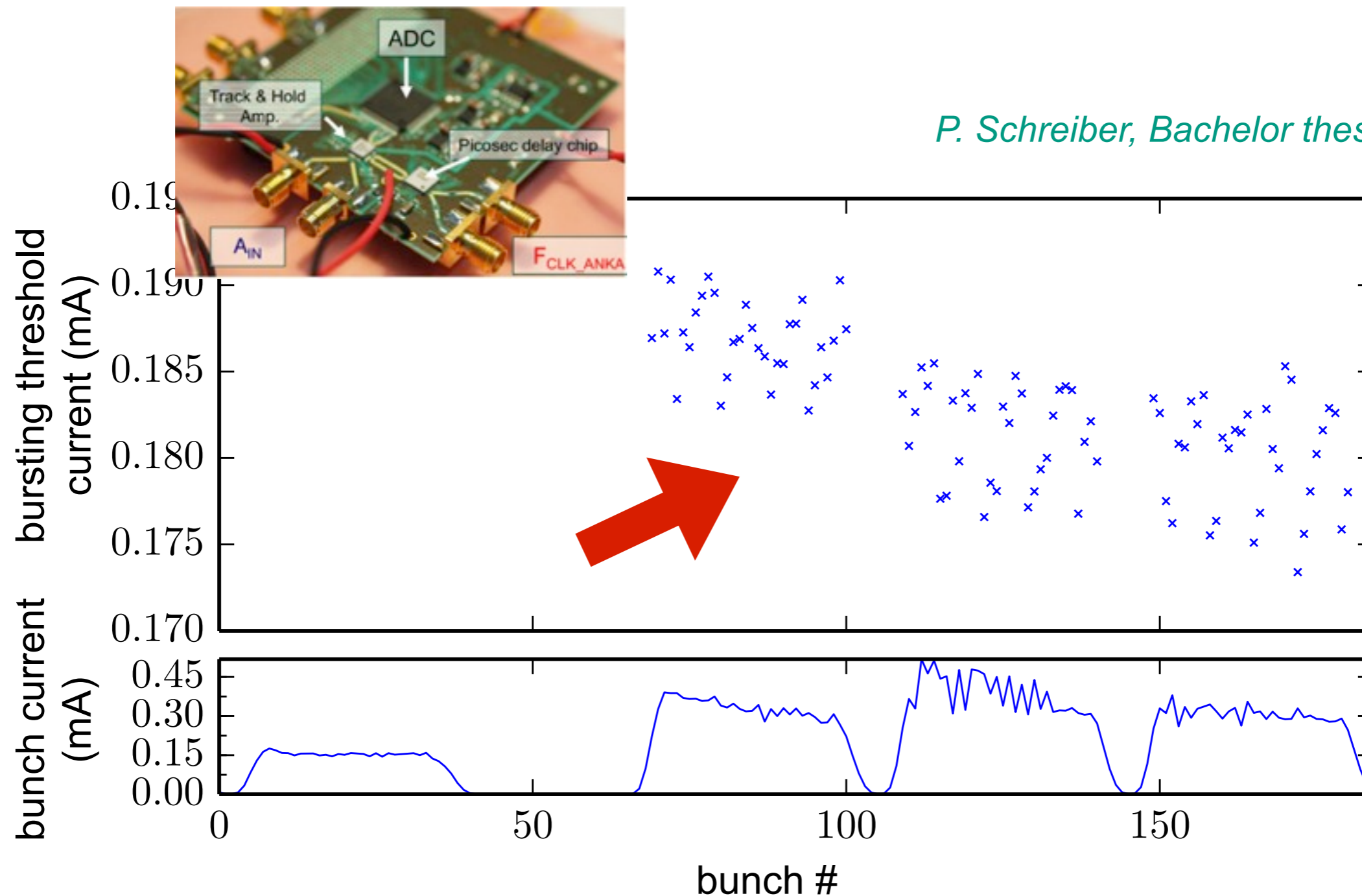
Instantaneous acquisition of full bursting spectrogram



M. Brosi, et al., IPAC 2015, MOPHA042

THz signal dynamics - development of detectors, readout & (online) analysis

P. Schreiber, Bachelor thesis

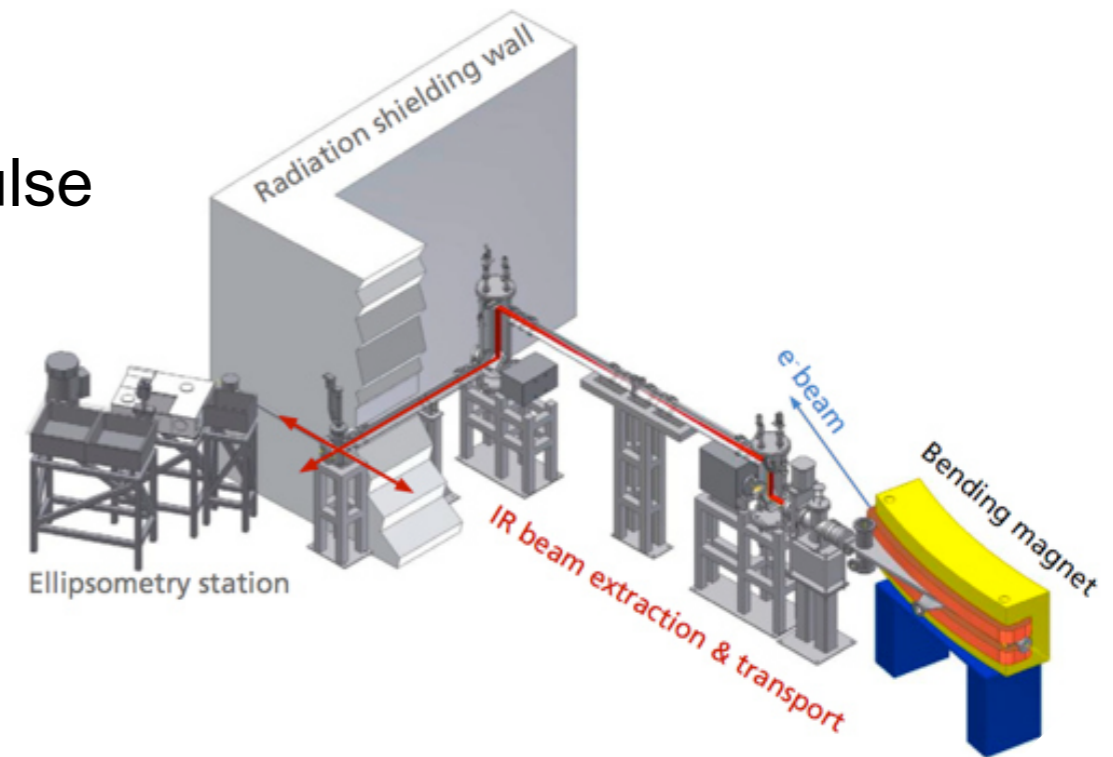
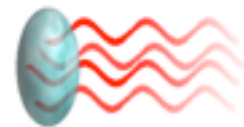


M. Caselle, M. Balzer, S. Chilingaryan, M. Hofherr, V. Judin, A. Kopmann, N.J. Smale, P. Thoma, S. Wuensch, A.-S. Müller, M. Siegel and M. Weber, An ultra-fast data acquisition system for coherent synchrotron radiation with terahertz detectors, IOPscience, Journal of Instrumentation 9, C01024 (2014).

Direct detection of bunch fields

■ Measurements in two basic set-ups

- detection of synchrotron radiation THz pulse in the beam line (“far-field”)
- (direct) detection of bunch electric field (“near-field”)



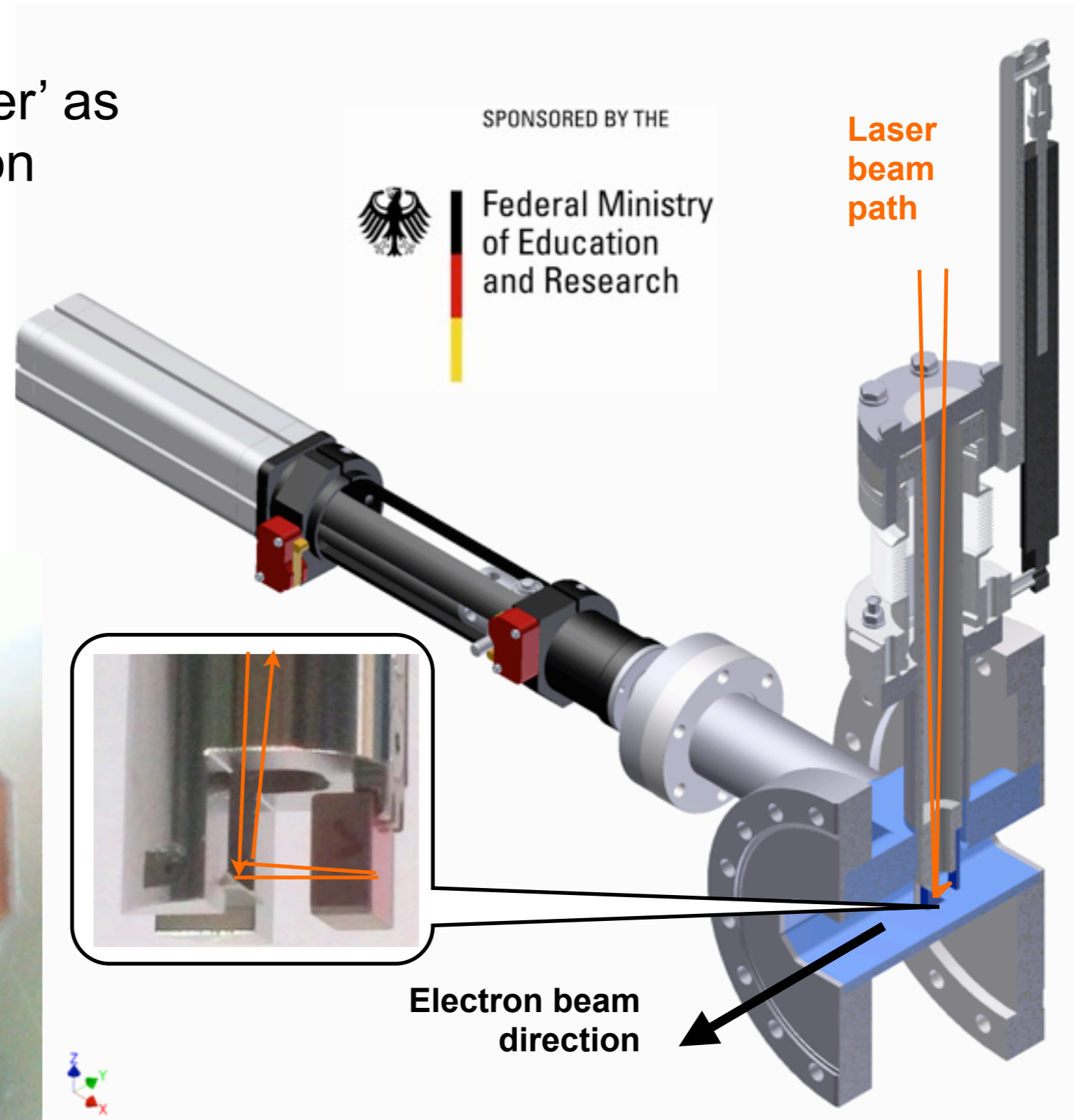
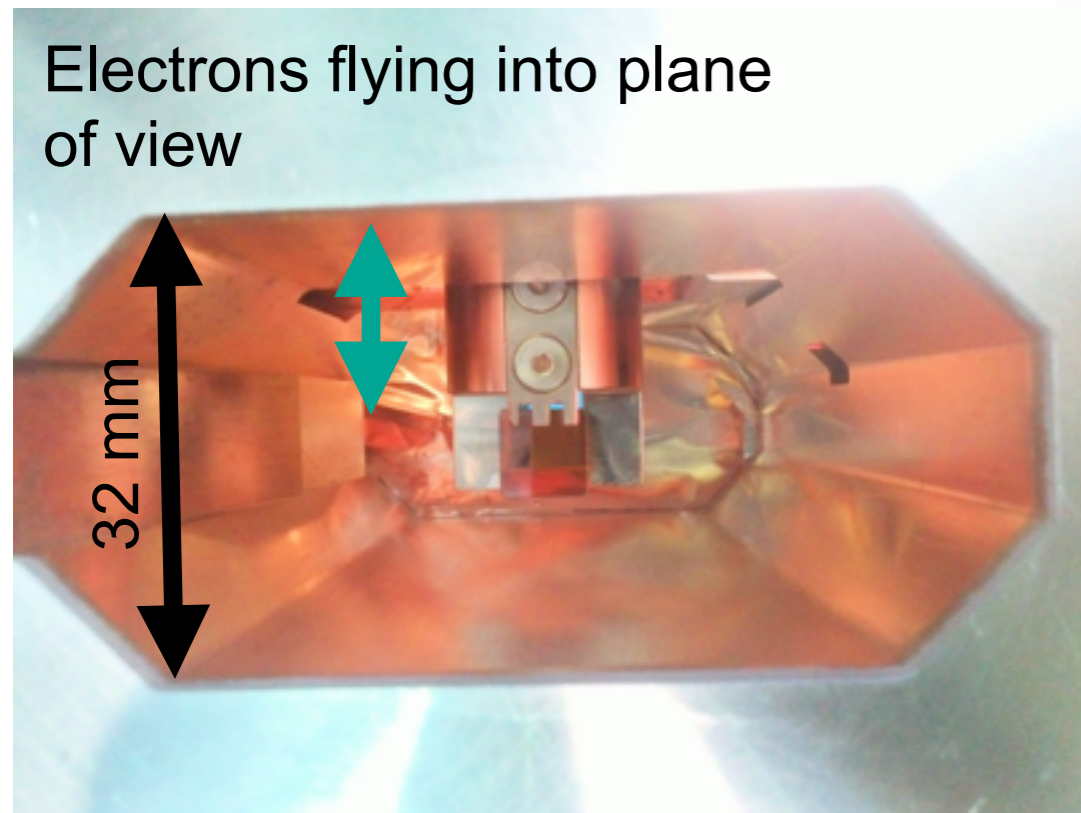
■ Electro-optic (EO) methods measure

- wake field (EO sampling)
- bunch shape (EO spectral decoding, single shot!)



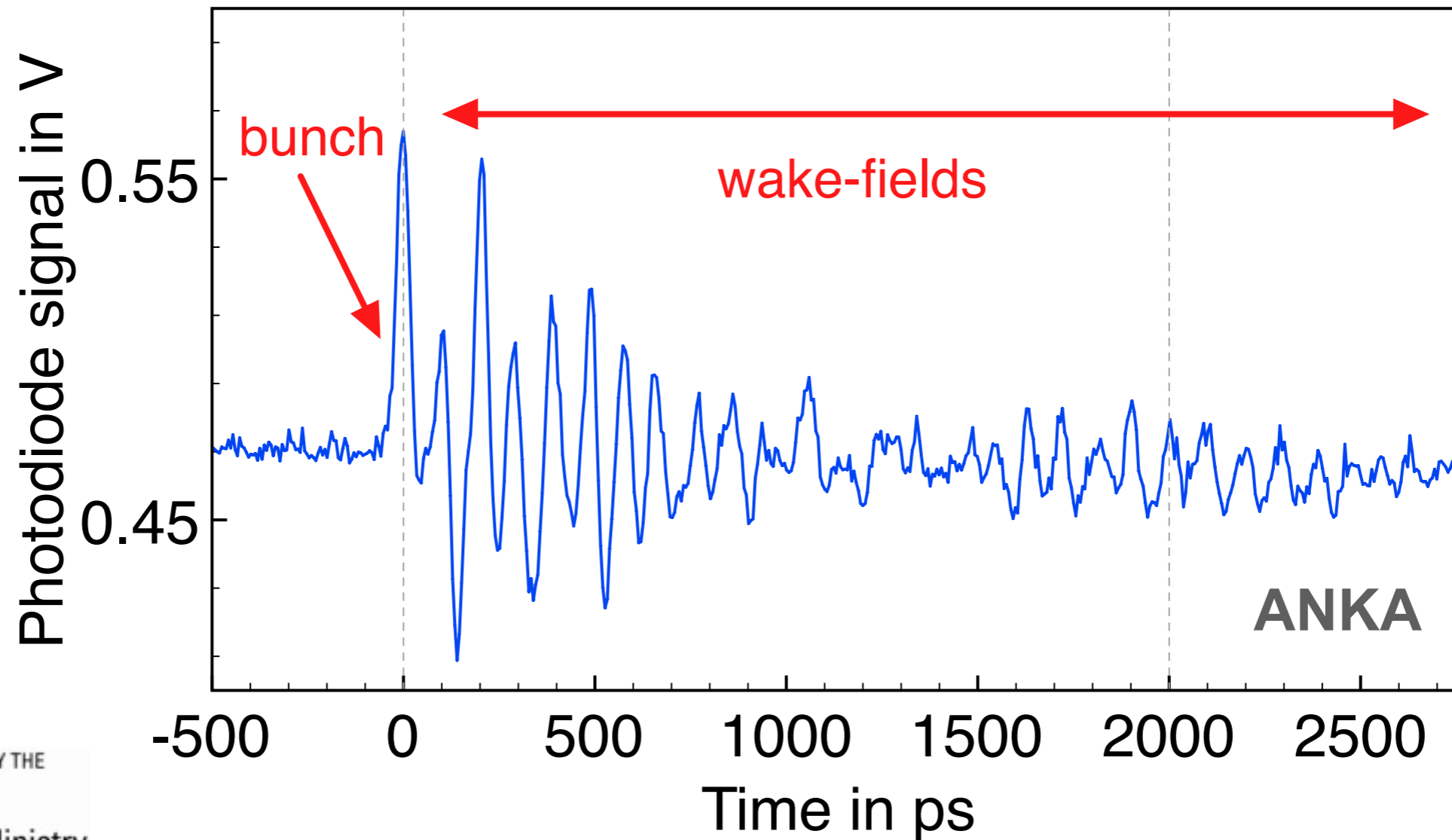
EO set-up in the ANKA vacuum chamber

- Retractable arm with 'slider' as shielding for user operation
- EO monitor designed at PSI & DESY adapted for use with ANKA



EO sampling: bunch & wake field

- EOS measurement of the E-field induced birefringence inside GaP crystal from passing bunch



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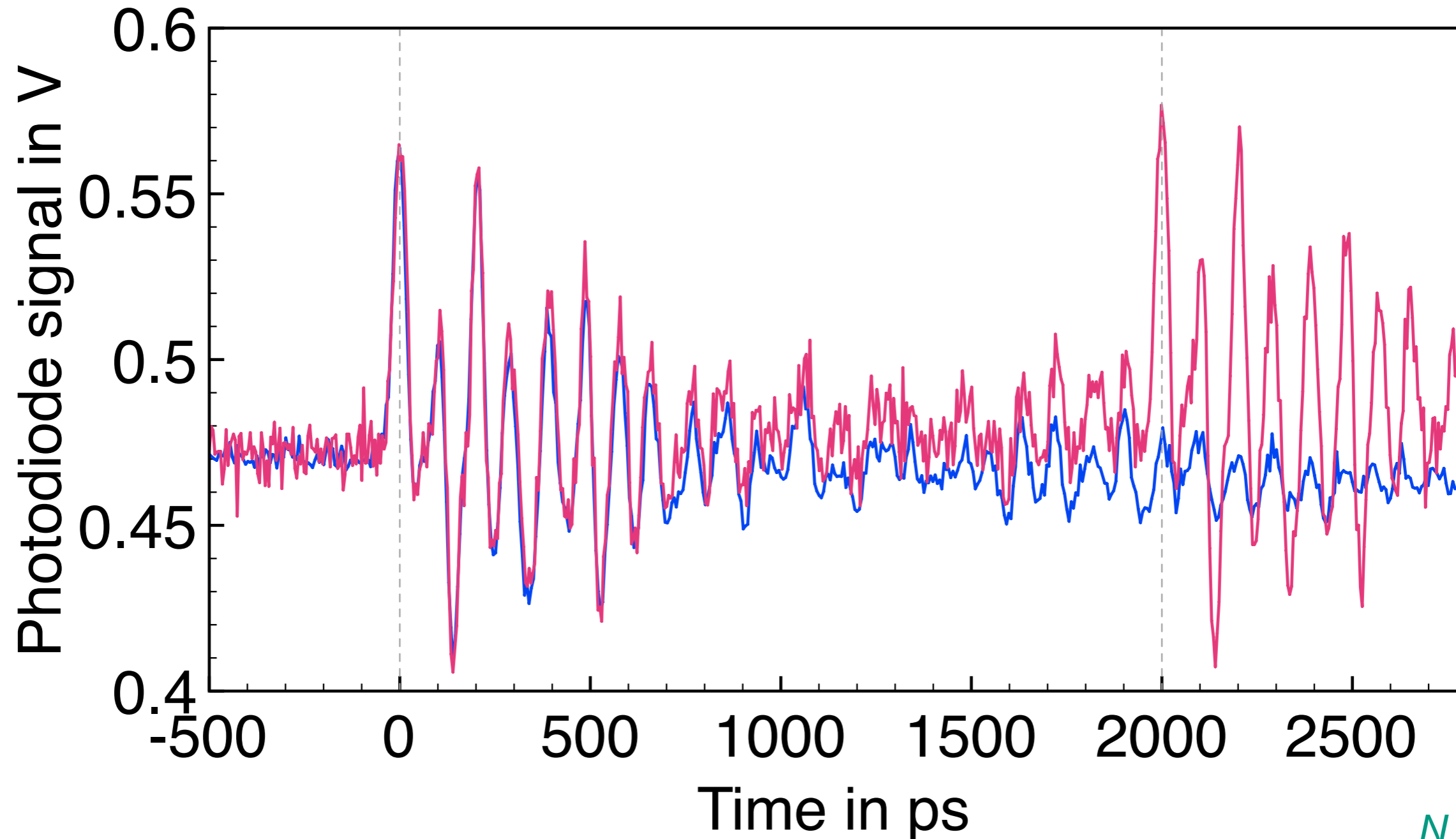


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N. Hiller et al., IPAC'13, MOPEA014
B. Kehrer et al., IPAC'13, MOPEA015

EOS with two consecutive bunches

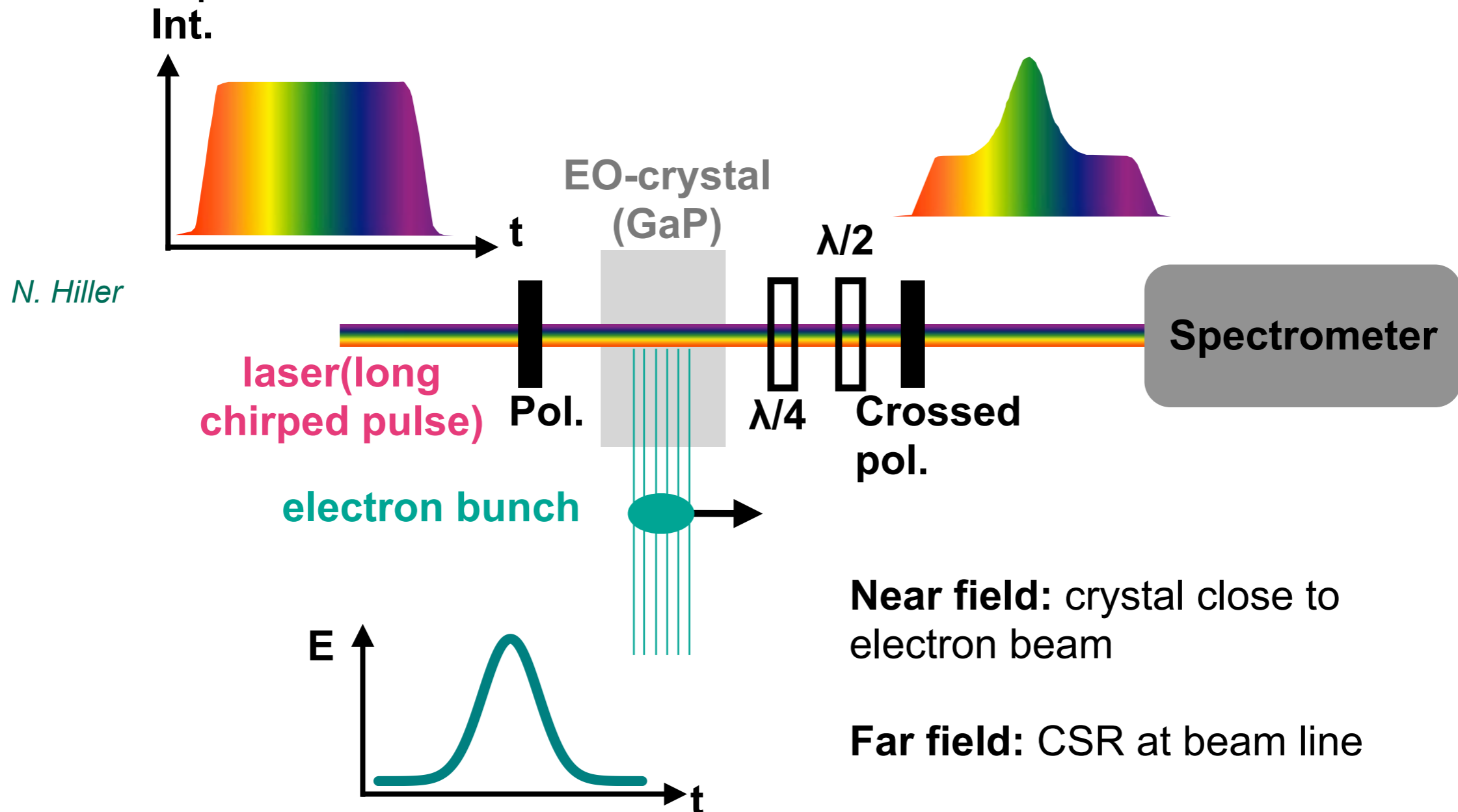
- blue: single bunch; red: 2-bunch fill (second bunch with lower current)



N. Hiller

Electro-Optical Spectral Decoding

- Single shot method: allows to record transient changes in longitudinal bunch profile

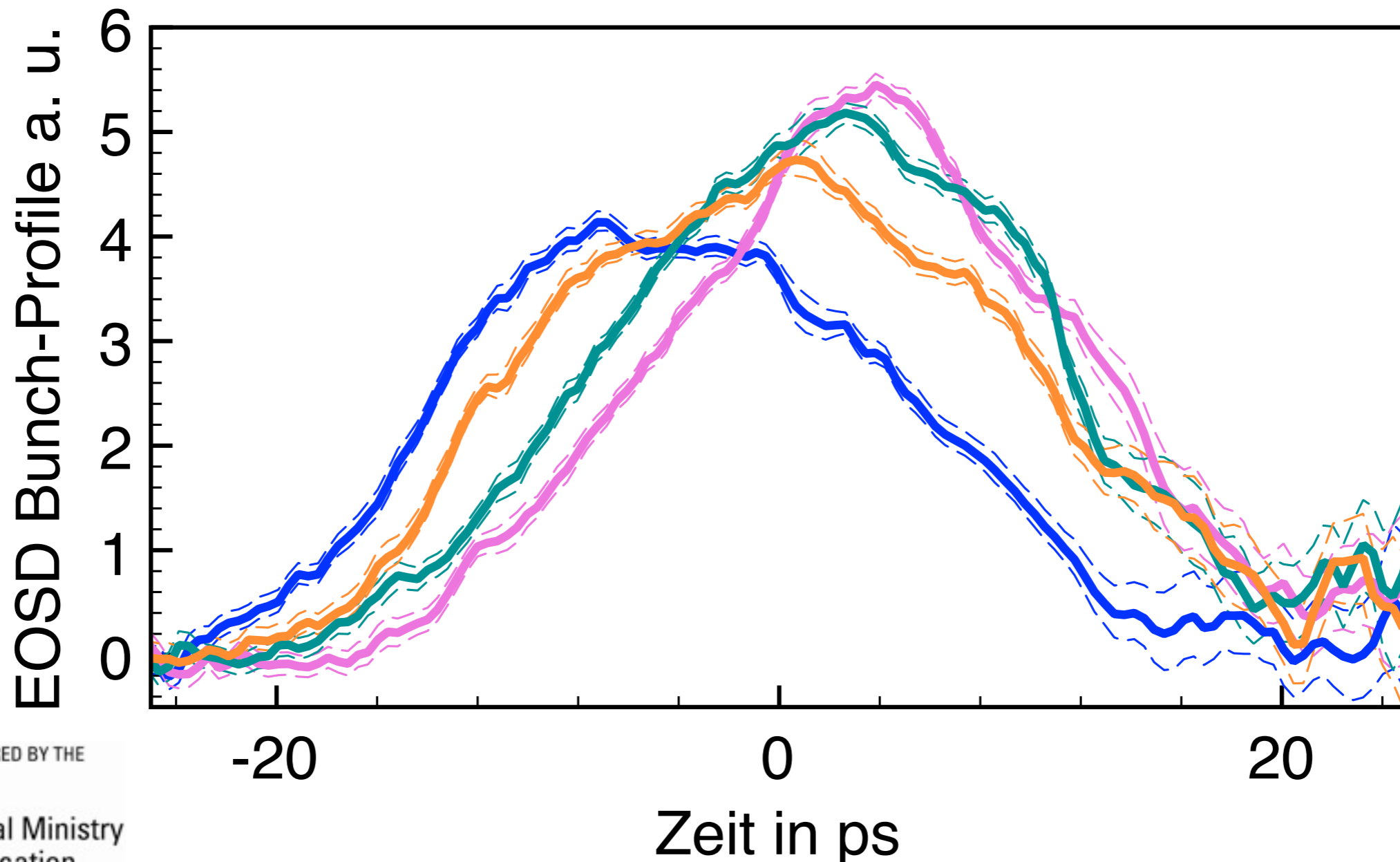


$\lambda/4$: compensate intrinsic birefringence of crystal
 $\lambda/2$: control transmission through crossed polariser

N. Hiller

EO spectral decoding: bunch shape

- Single shot EOSD measurements indicate dynamic sub-structures



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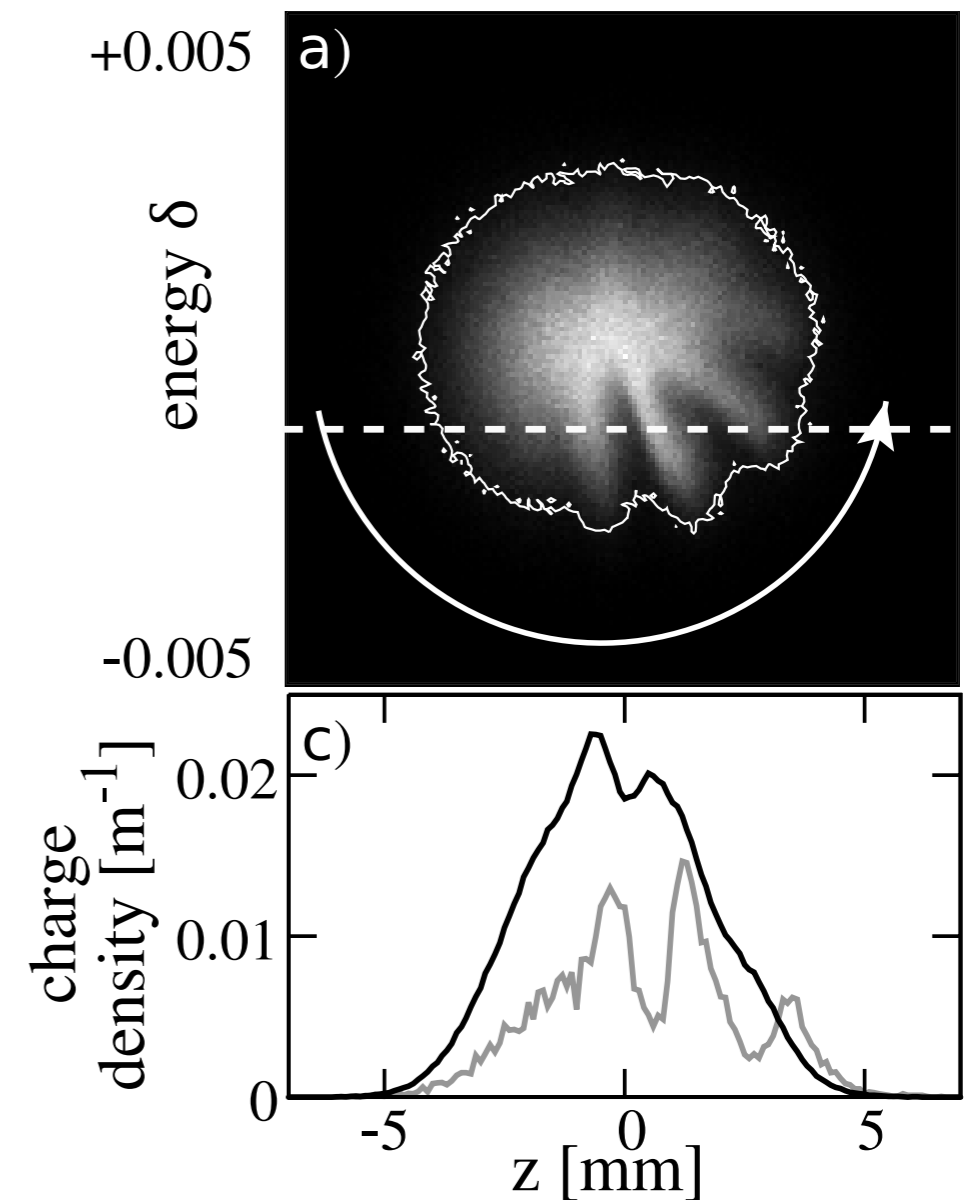
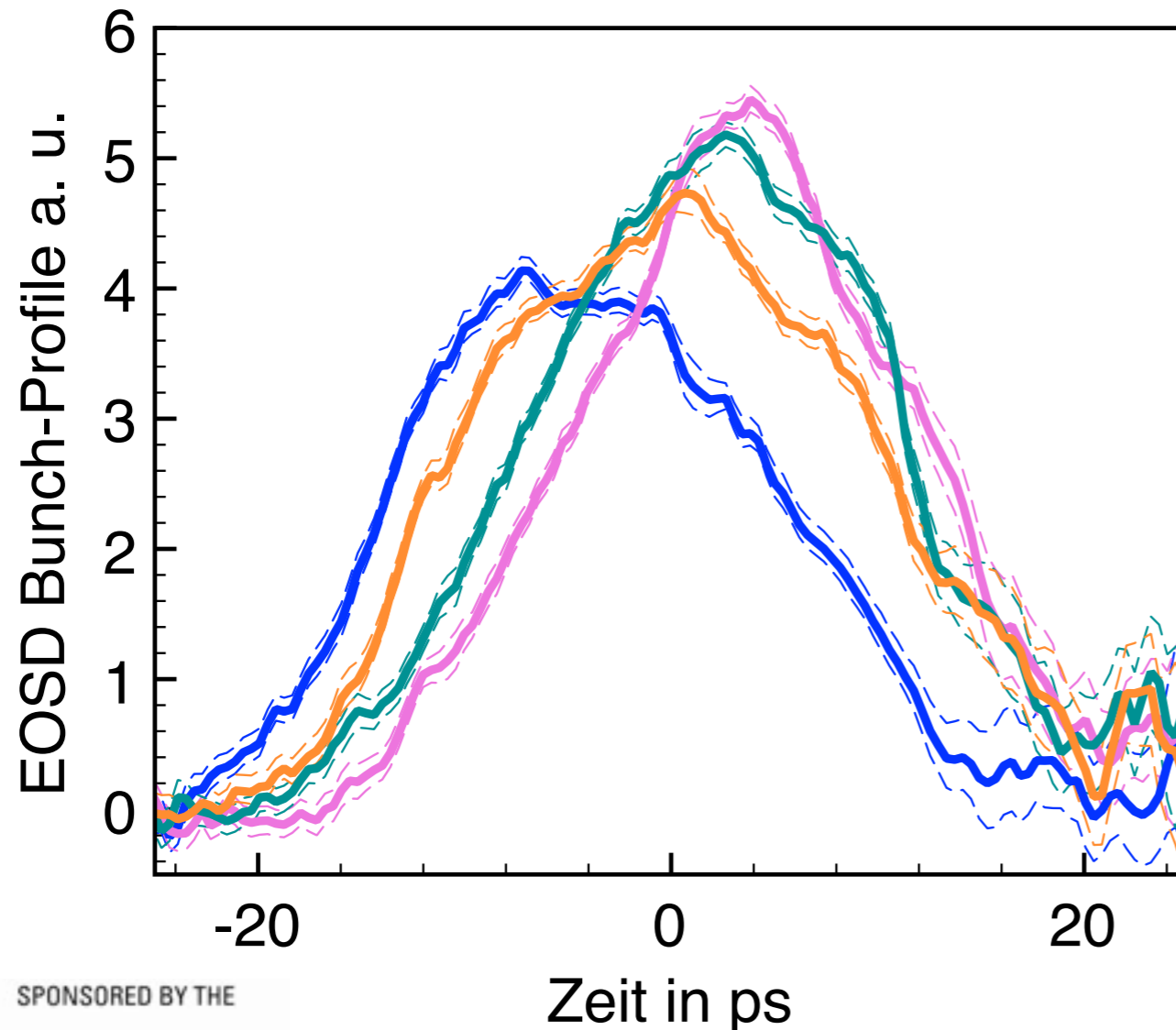


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N. Hiller

EO spectral decoding: bunch shape

- Single shot EOSD measurements indicate dynamic sub-structures



C. Evain et al.,
EPL, 98 (2012) 40006

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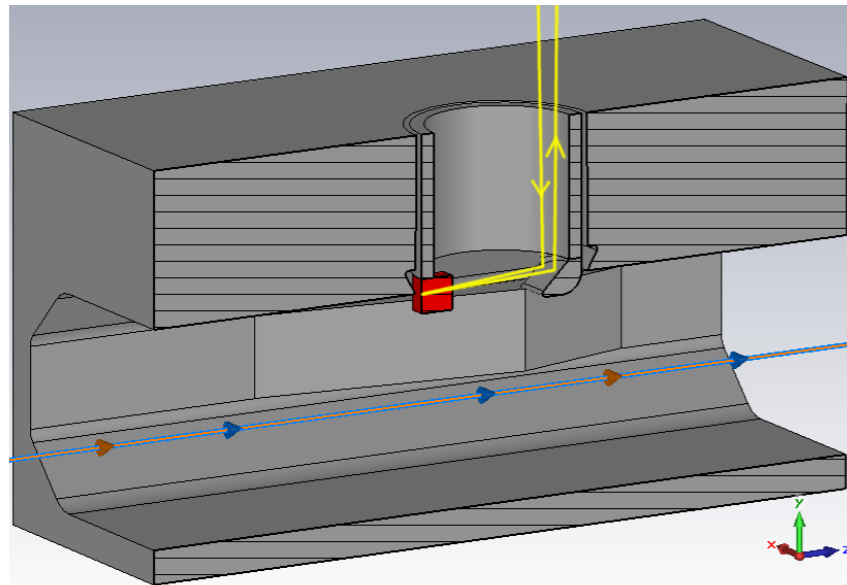


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N. Hiller

EO - Upgrades at ANKA

- Studies to reduce the effects of wake-fields in the vacuum chamber



P. Schönfeldt et al., IPAC2015 MOPHA038

- Ultra-fast linear detector array with MHz rep. rate

Readout rate of commercial InGaAs spectrometers is limited to ~100 kHz

Aim: 2.7 MHz (XFEL 5 MHz)

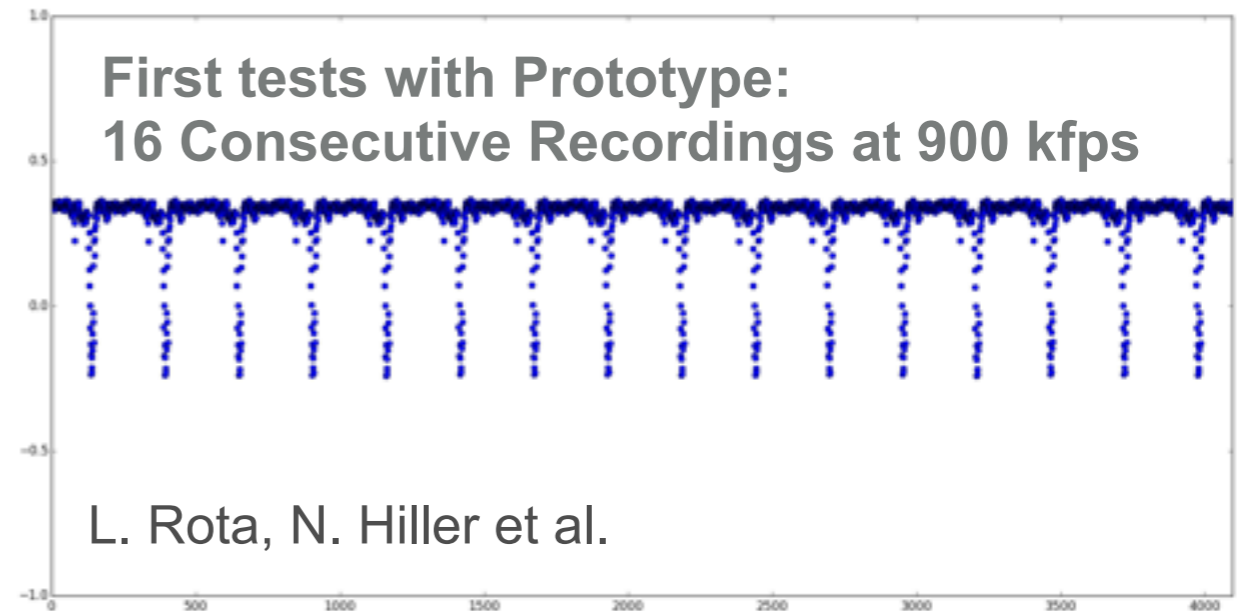
Applications: turn-by-turn long. & transv. profiles

Scientific collaboration:

- Hardware & partly software implementation of daughter card
- Fast readout based on PCIe/DMA
- Real-time GPU data evaluation

- GOTTHARD front end development
- Si arrays

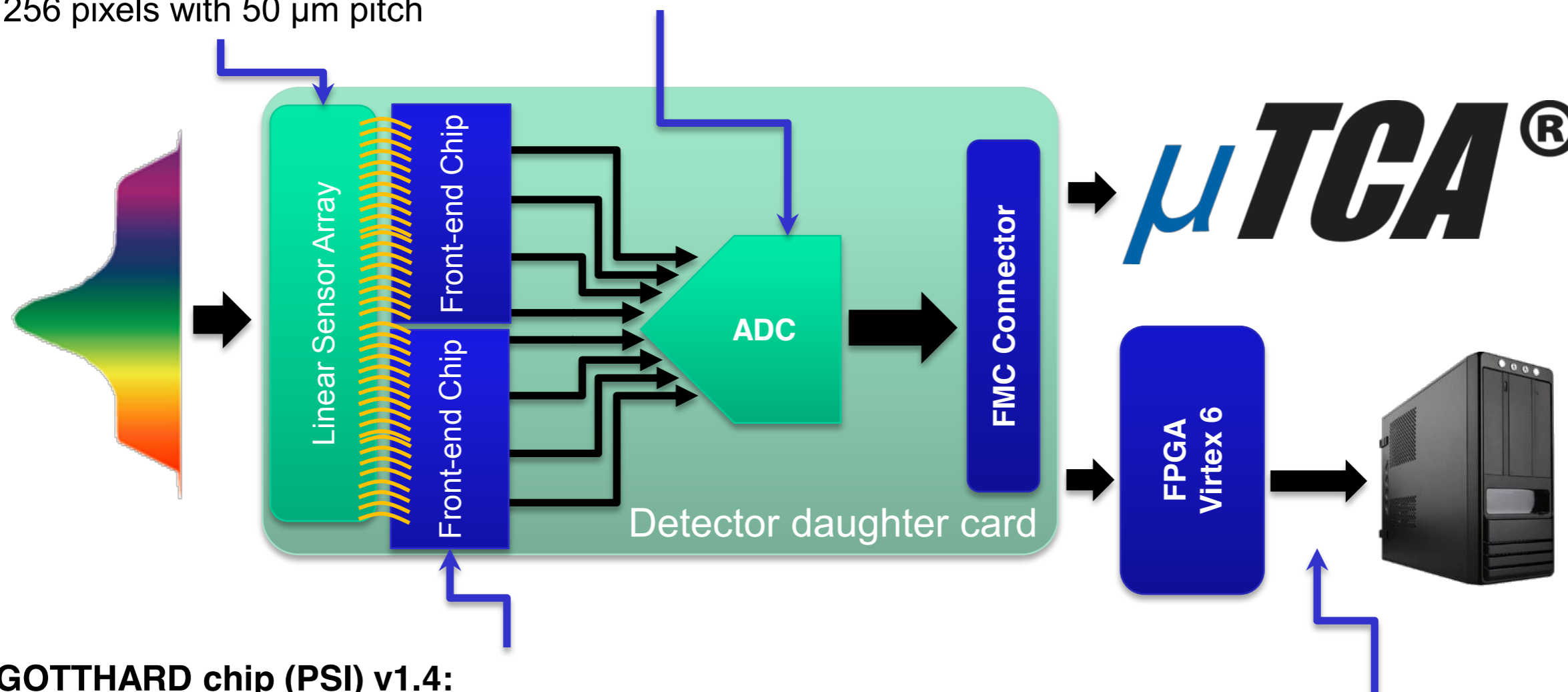
- Firmware for daughter card control
- μTCA integration



Setup - Version 1: 900 kfps (2015, now)

InGaAs (Xenics) / Si (PSI):
256 pixels with 50 μm pitch

ADC9252: 8 channels @ 14-bit, 50 MSPS

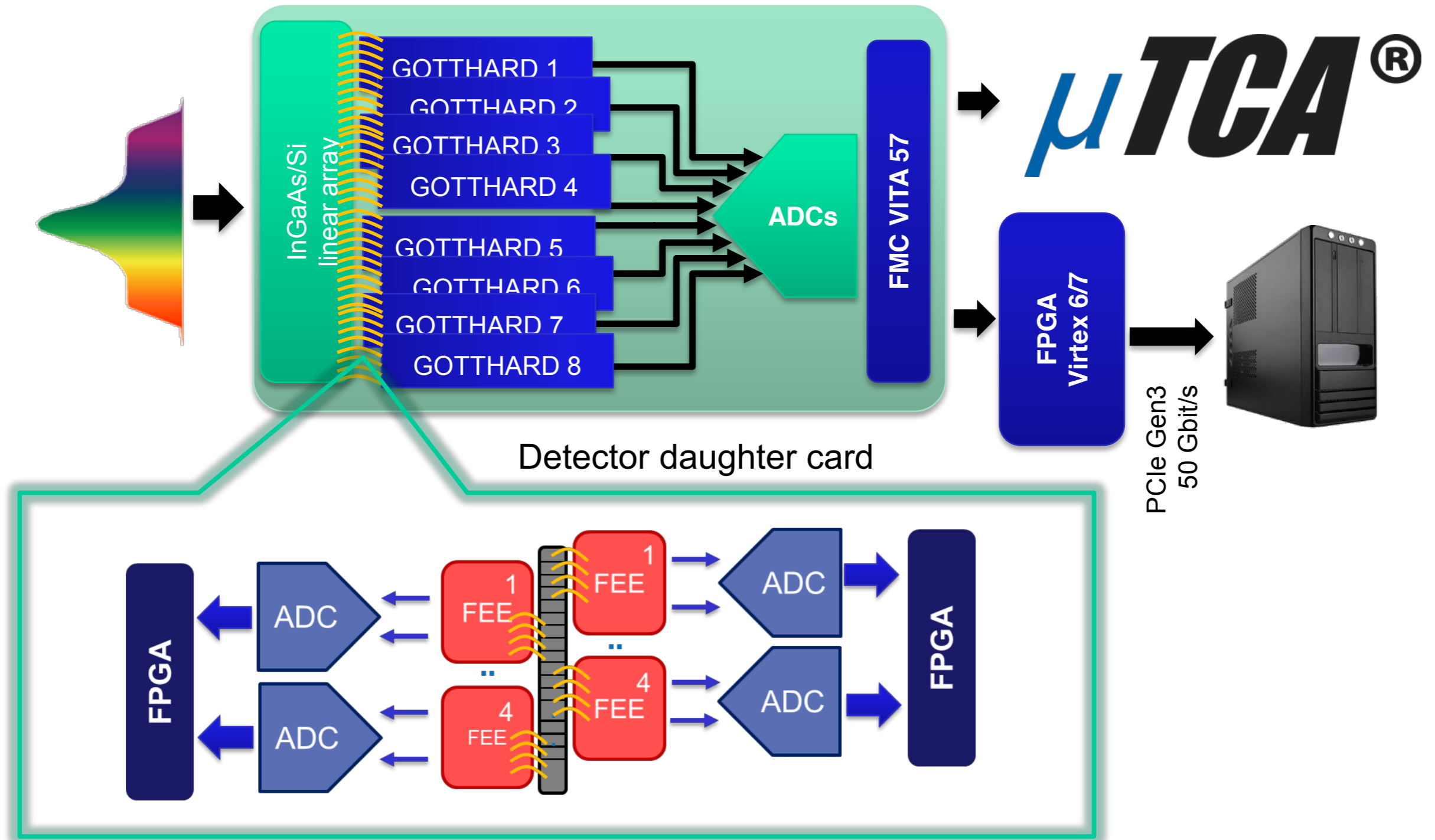


GOTTHARD chip (PSI) v1.4:

Gain Optimizing microstrip system with Analog Readout
Charge Integrating readout for XFEL strip-detector - IBM 0.13 μm
128 inputs, 4 analog outputs operating at 32 MHz
Max. read-out rate: 1 Mfps

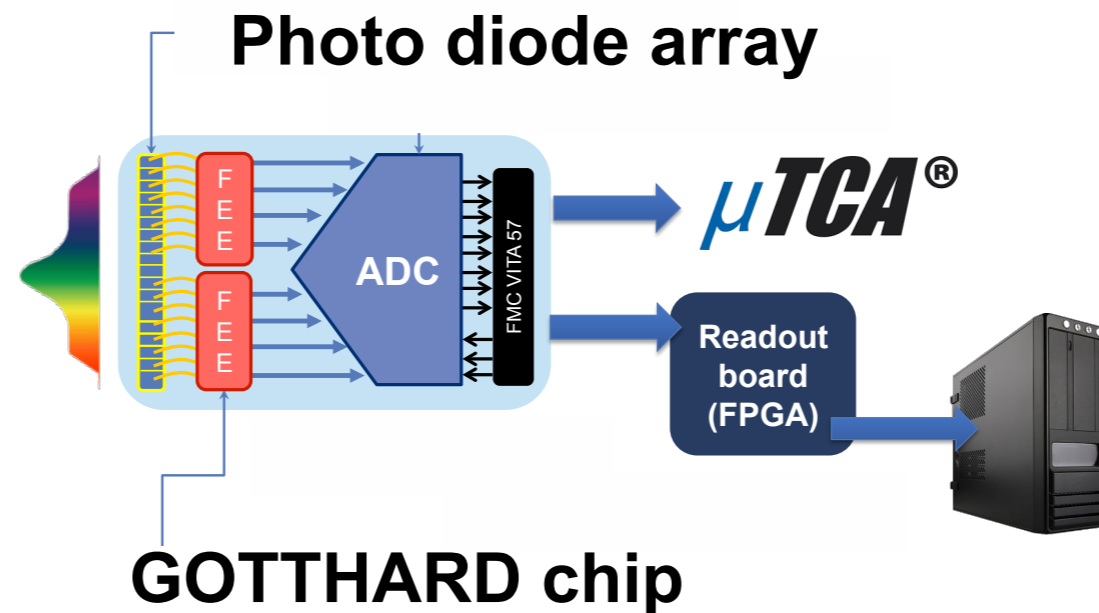
Fast KIT-DAQ:
Based on PCIe/DMA

Setup - Version 2: 5 Mfps (2015/2016)



Ultra-Fast Line Array Collaboration

Scientific collaboration:



- Hardware & partly software implementation of daughter card
- Fast readout based on PCIe/DMA
- Real-time GPU data evaluation



- GOTTHARD front end development
- Si arrays

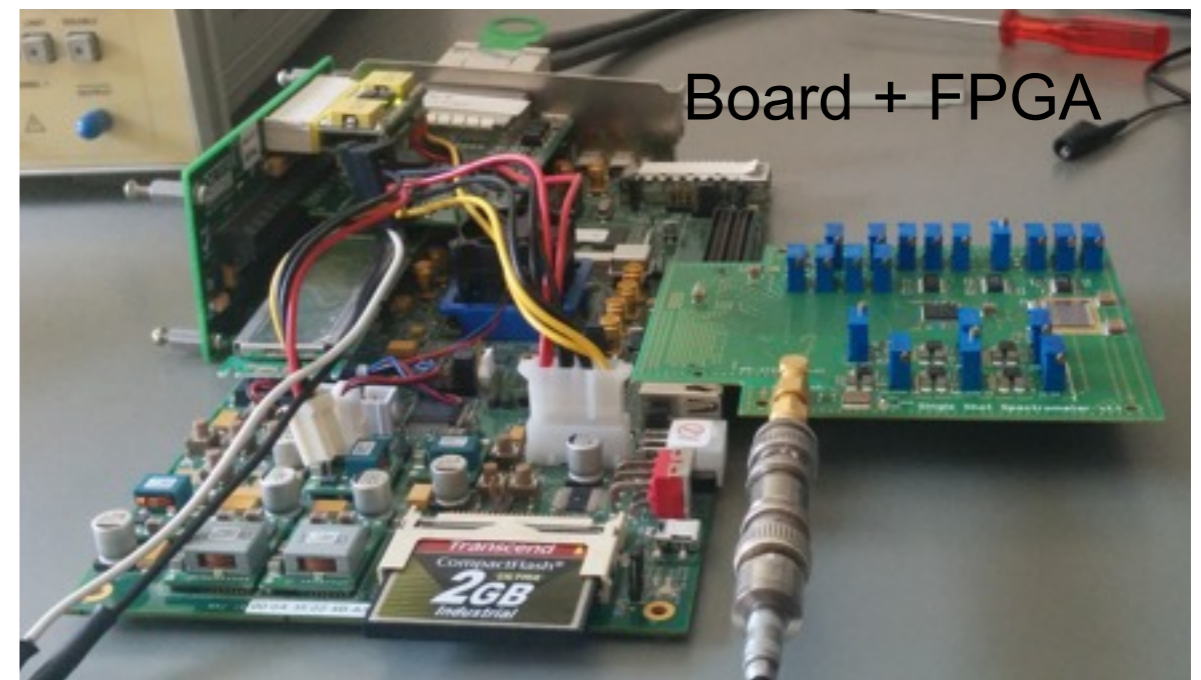
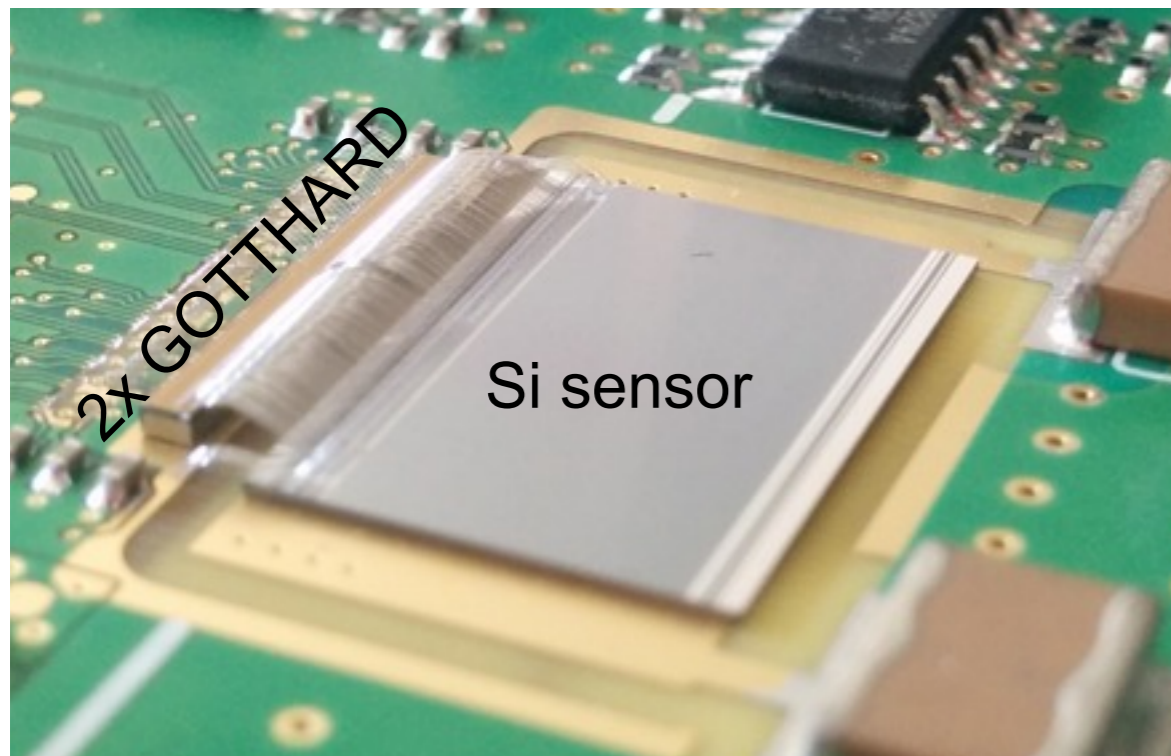
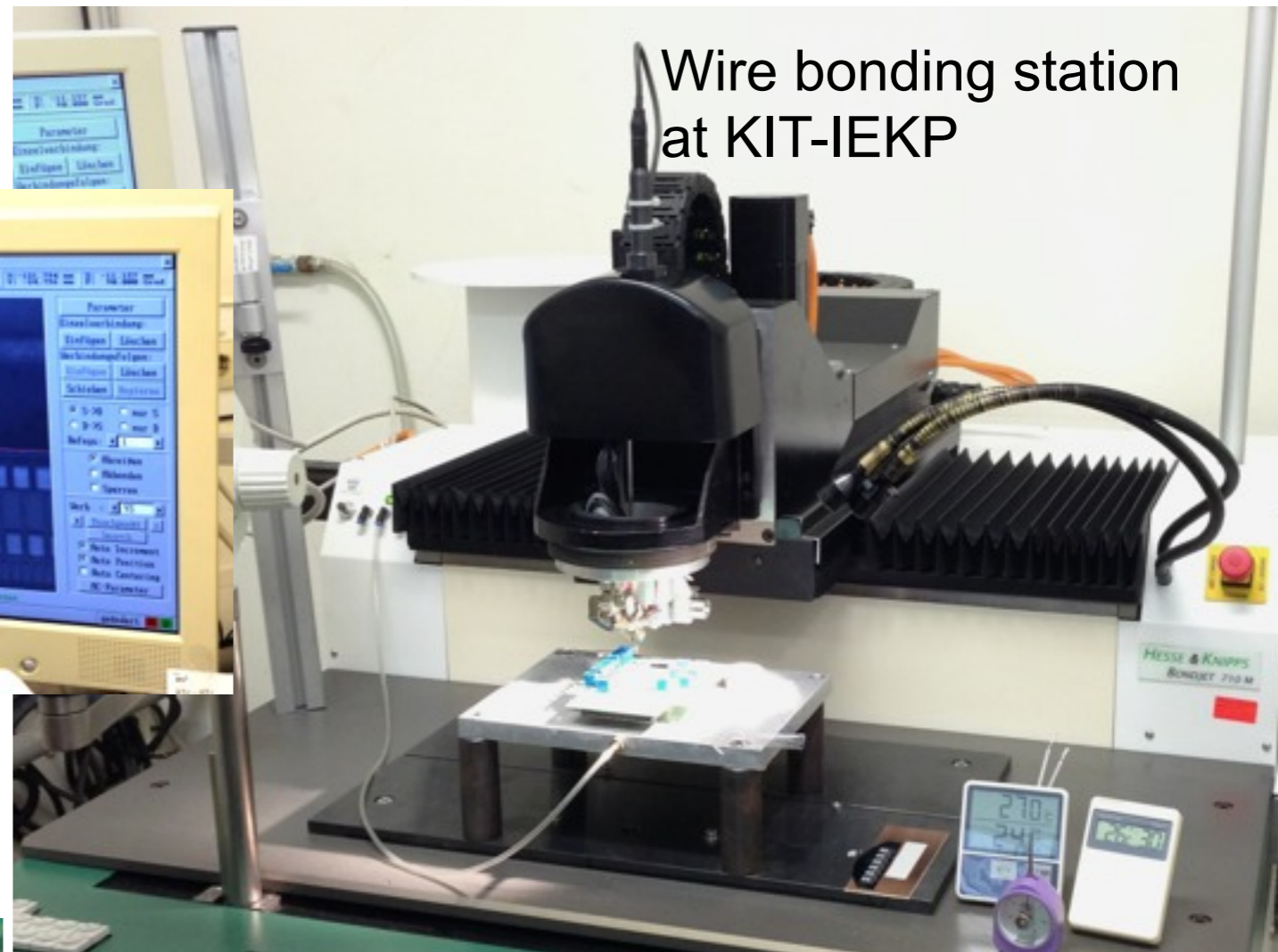
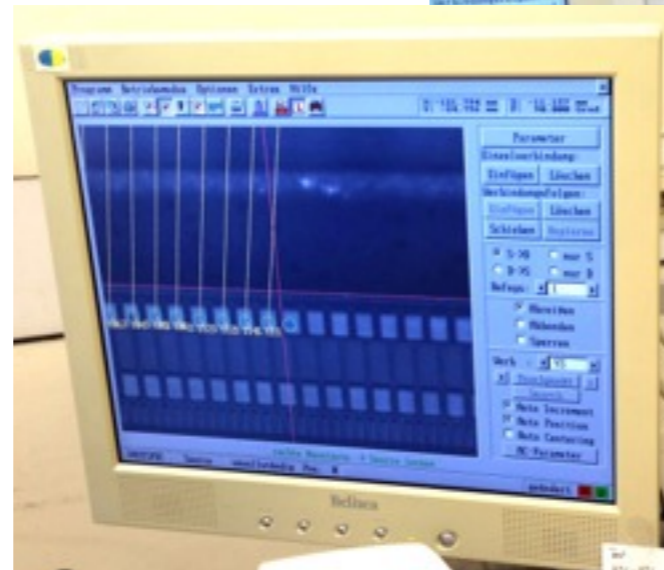


Lodz University of Technology

- Firmware for daughter card control
- μTCA integration

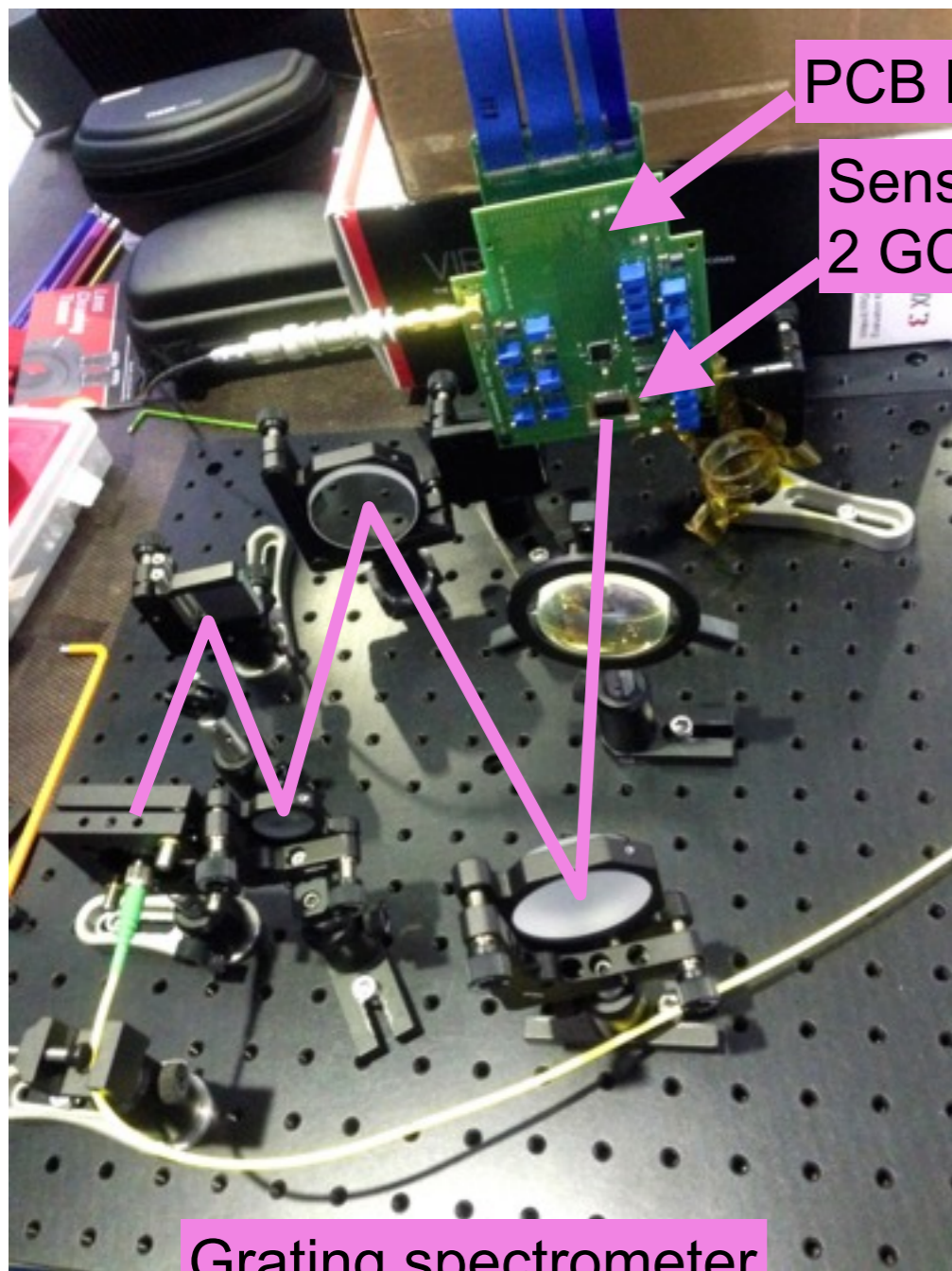
In-House Hybrid Assembly

- In-House glueing & wire-bonding at KIT 29th May 2015
- First bonded the Si sensor, InGaAs will follow now



First tests with the Prototype & Laser

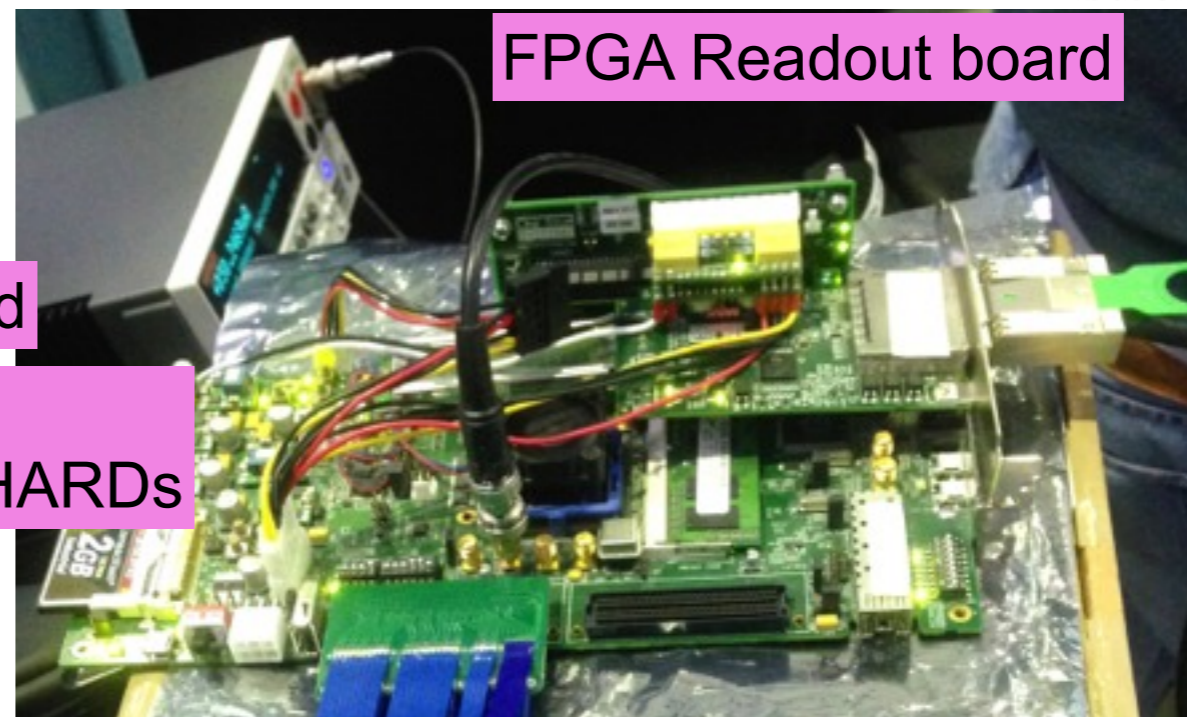
10th June 2015



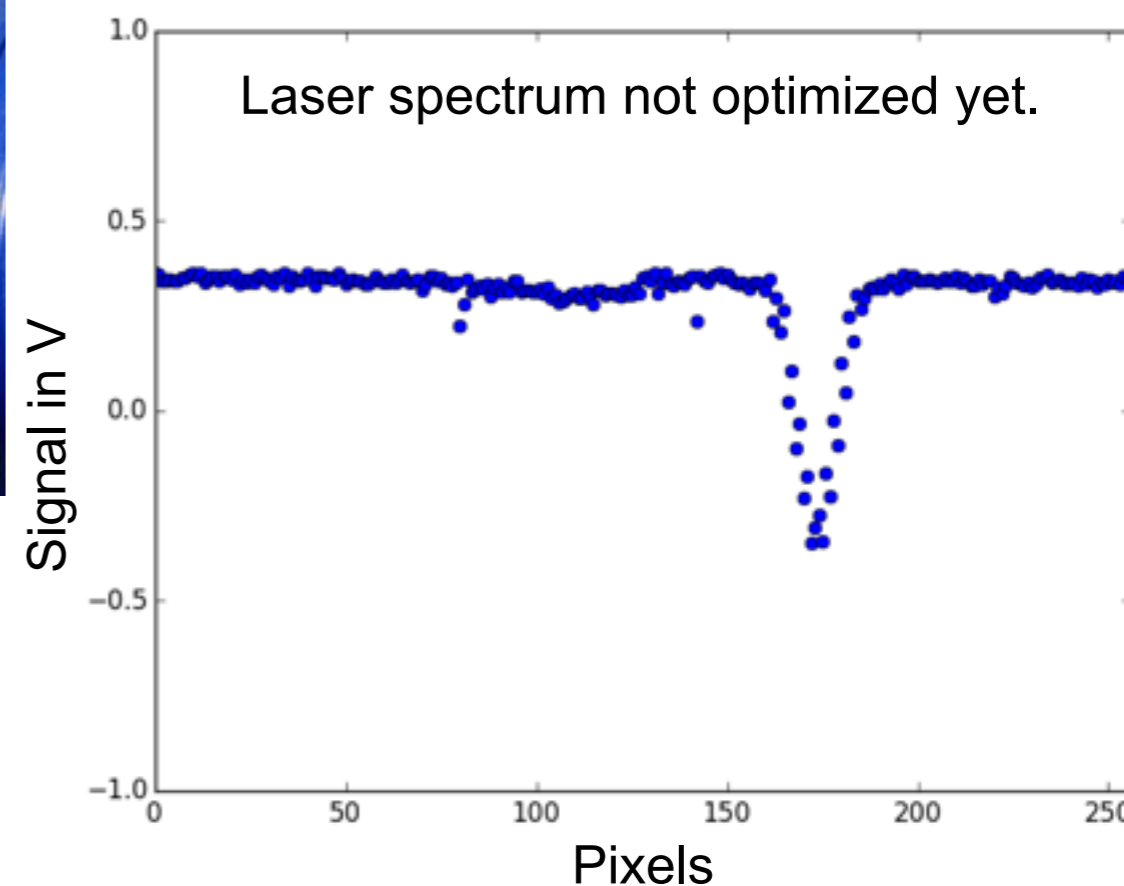
PCB board

Sensor +
2 GOTTHARDS

Grating spectrometer

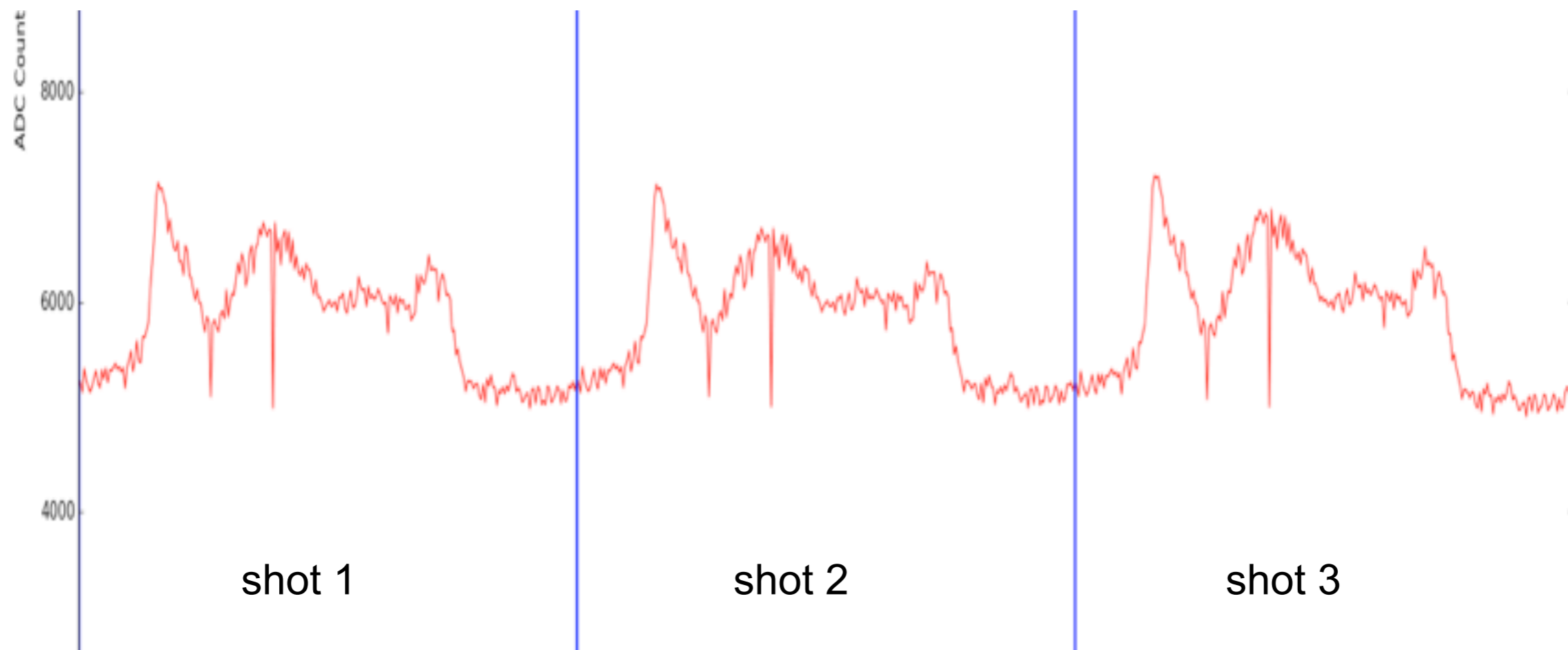


FPGA Readout board



Three consecutive laser spectra

- Last week: laser spectrum with InGaAs sensor for 3 consecutive laser shots, recorded at 900 kfps.

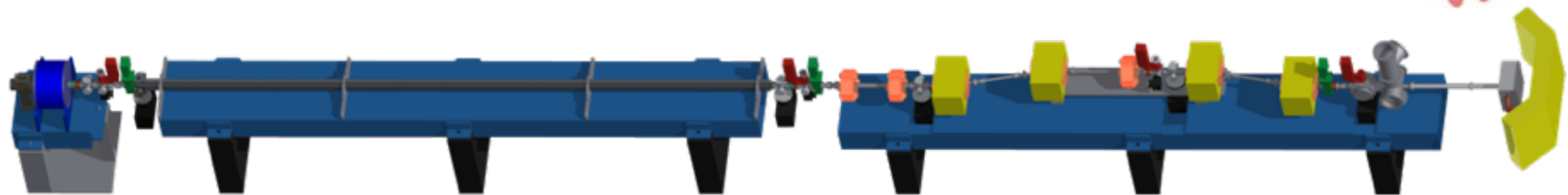
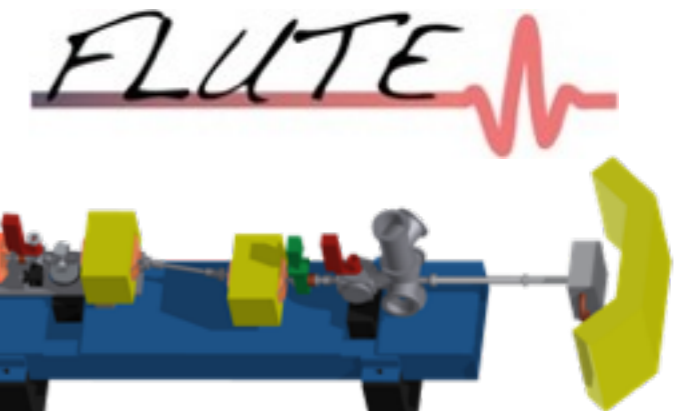


L. Rota, N. Hiller et al.

- EO spectral decoding with 900 kfps now possible!

FLUTE: Accelerator test facility at KIT

- FLUTE (Ferninfrarot Linac- Und Test-Experiment)
 - Test facility for **accelerator physics within ARD**
 - **Experiments** with THz radiation



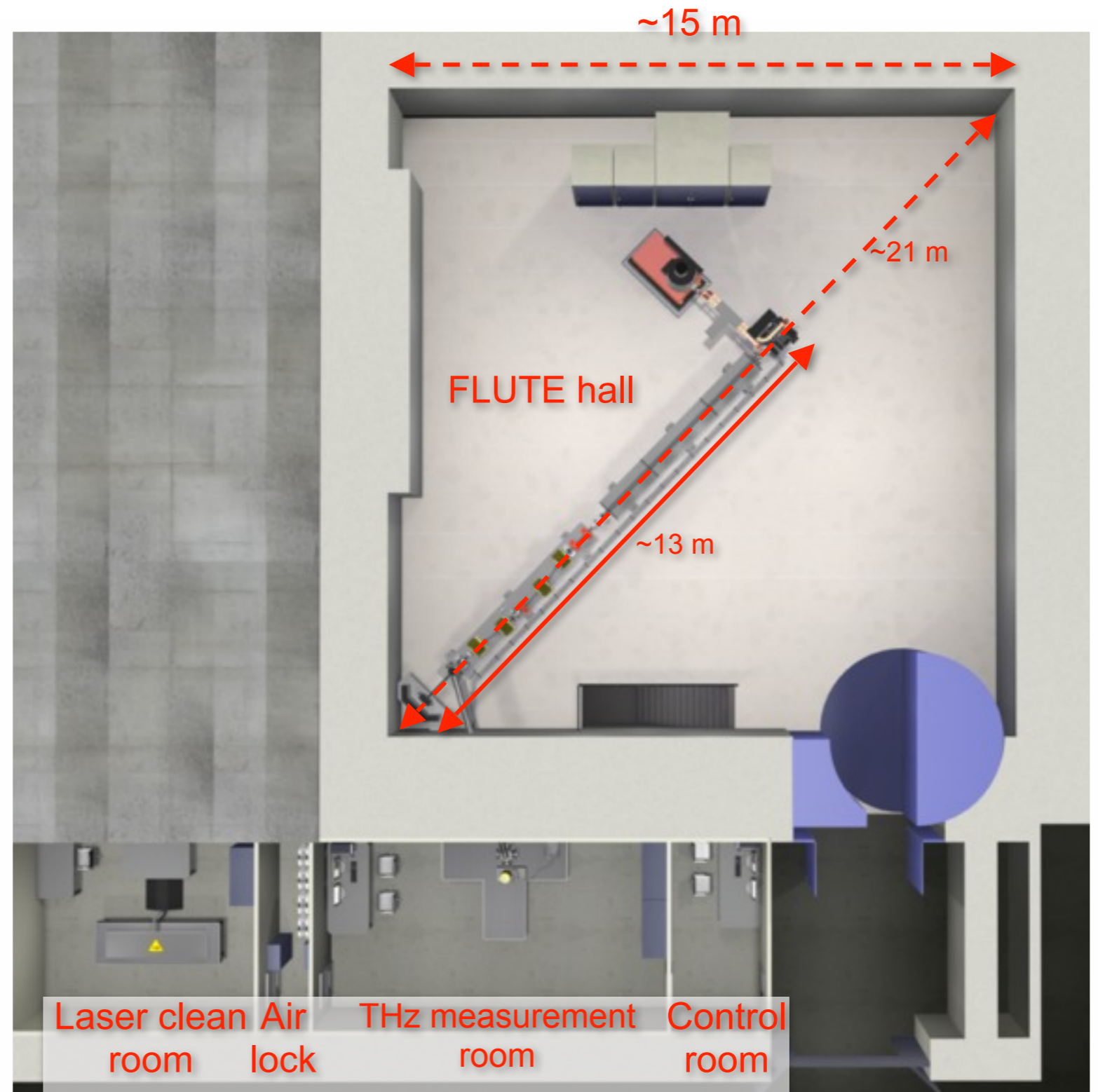
- Serve as a test bench for new beam diagnostic methods and tools
- Develop single shot fs diagnostics
- Synchronization on a femtosecond level
- Systematic bunch compression studies
- Generate intense THz radiation
- Compare different coherent THz radiation generation schemes in simulation and experiment

Final electron energy	~ 41	MeV
Electron bunch charge	0.001 - 3	nC
Electron bunch length	1 - 300	fs
Pulse repetition rate	10	Hz
THz E-Field strength	up to 1.2	GV/m

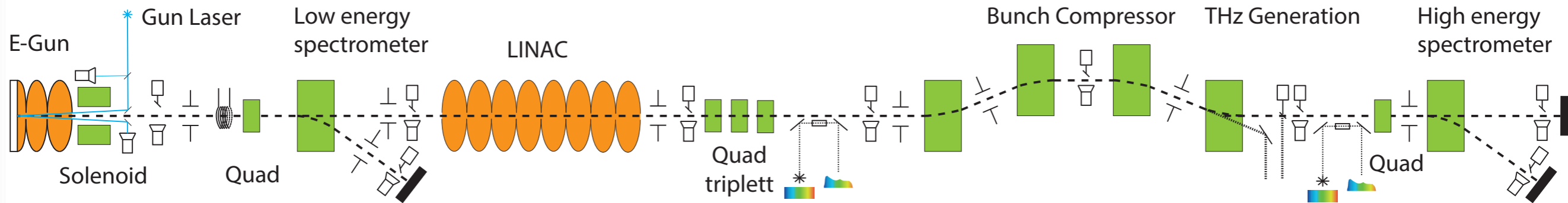
M. Nasse et al. , Rev. Sci. Instrum. 84, 022705 (2013)

FLUTE Layout & Hardware

- Civil engineering finished
- Gun laser operational
 - Transport system in planning
 - Laser sync in preparation
- RF system in assembly
 - Klystron and waveguide delivered
 - New linac module
 - LLRF system shipped from DESY
- Magnets in progress
 - Solenoid on test bench
 - Dipole design studies



Diagnostics



■ Large dynamic range:

- Charge: 1 pC - 3 nC
- Energy: 7 - 42 MeV
- Bunch length: 2-3 ps (after gun), few fs (after chicane)
- Transverse bunch size: 20 μm - 4 mm

■ Charge, position, size:

- Integrating current transformer
- Faraday cup
- 7-8 cavity BPMs (XFEL, SwissFEL)
- 6 movable screens (PSI)

■ Energy:

- 2 spectrometers (7 & 42 MeV)

■ Bunch length:

- 2 electro-optical monitors (PSI / DESY)

■ Laser-Diagnostic:

- Virtual cathode
- Cathode imaging
- Auto-Correlator / Grenouille

■ THz-Diagnostic:

- Fast THz-detectors (e.g. HEB, Schottky Diodes)
- Martin-Puplett interferometer
- Michelson interferometer
- Electro-optical methods (far-field)

N. Hiller, B. Smit

Summary

- A large variety of technologies, methods and competences are available for accelerator R&D at KIT

- Accelerator technologies under development include, e.g.
 - superconducting insertion devices
 - ultra-fast radiation detectors from the X-ray to the THz regime
 - high data-throughput data acquisition systems for beam diagnostics with MHz repetition rates

- Accelerator test facilities
 - 2.5 GeV electron storage ring (ANKA)
 - 50 MeV fs linear electron accelerator (FLUTE)

- Open for new ideas/cooperations